

MZ-E80

SERVICE MANUAL

Ver 1.1 2000. 05
With SUPPLEMENT-1
(9-927-132-82)

E Model
Tourist Model



Photo: Silver

US and foreign patents licensed from Dolby Laboratories Licensing Corporation.

Model Name Using Similar Mechanism	MZ-E55
Mechanism Type	MT-MZE55-150
Optical Pick-Up Name	ODX-1B

SPECIFICATIONS

System

Audio playing system

MiniDisc digital audio system

Laser diode properties

Material: GaAlAs

Wavelength: $\lambda = 790 \text{ nm}$

Emission duration: continuous

Laser output: less than $44.6 \mu\text{W}^*$

* This output is the value measured at a distance of 200 mm from the objective lens surface on the optical pick-up block with 7 mm aperture.

Revolutions

800 rpm to 1800 rpm (CLV)

Error correction

Advanced Cross Interleave Reed Solomon Code (ACIRC)

Sampling frequency

44.1 kHz

Coding

Adaptive TRansform Acoustic Coding (ATRAC)

Modulation system

EFM (Eight to Fourteen Modulation)

Number of channels

2 stereo channels

1 monaural channel

Frequency response

20 to 20,000 Hz $\pm 3 \text{ dB}$

Wow and Flutter

Below measurable limit

Outputs

Headphones: stereo mini-jack, maximum output level 5 mW + 5 mW, load impedance 16 ohms

General

Power requirements

Nickel metal hydride rechargeable battery NH-14WM (supplied)

One LR6 (size AA) battery (not supplied)

Sony AC Power Adaptor AC-E15L¹⁾ (not supplied) connected to the DC IN 1.5 V jack

Battery operation time

You can check the battery condition with the battery indication which is displayed while using the player.

- Battery power decreasing
- ↓
- Weak batteries. Replace/recharge the batteries
- ↓
- The batteries have gone out. "LoBATT" flashes in the display of the remote control, and the power goes off.

Battery life*

Batteries	Playback
Ni-MH rechargeable battery (NH-14WM)	Approx. 16 hours**
One LR6 (size AA) alkaline battery	Approx. 22 hours
One LR6 (size AA) alkaline battery and a Ni-MH rechargeable battery (NH-14WM)	Approx. 42 hours**

* The battery life may be shorter depending on operating conditions and the temperature of the location.

** With a fully charged battery

Dimensions

Approx. 81 x 18.7 x 83.5 mm (w/h/d)
($3\frac{1}{4} \times \frac{3}{4} \times 3\frac{3}{8} \text{ in.}$) not including projecting parts and controls

Mass

Approx. 100 g (3.6 oz.) the player only
Approx. 145 g (5.2 oz.) incl. a premastered MD and a nickel metal hydride rechargeable battery NH-14WM

Supplied accessories

Battery Charger (1)
Rechargeable battery (1)
Rechargeable battery carrying case (1)
Headphones with a remote control (1)
Dry battery case (1)
Hand strap (1)
AC Plug Adaptor (1) (Tourist model only)

Design and specifications are subject to change without notice.

PORTABLE MINIDISC PLAYER

SONY[®]



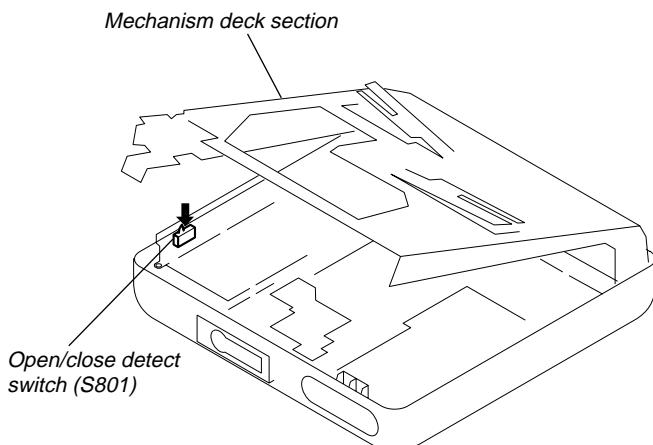
MICROFILM

SECTION 1 SERVICING NOTES

TABLE OF CONTENTS

1. SERVICING NOTES	2
2. GENERAL	3
3. DISASSEMBLY	4
4. TEST MODE	6
5. ELECTRICAL ADJUSTMENTS	10
6. DIAGRAMS	
6-1. Block Diagram	11
6-2. Printed Wiring Boards	16
6-3. Schematic Diagram	19
6-4. IC Pin Function Description	28
7. EXPLODED VIEWS	35
8. ELECTRICAL PARTS LIST	37

- Removing the mechanism deck causes this set to be disabled during a repair with the power supplied to the set. Therefore, lock convex portion of open/close detect switch (S801) during a repair.



- Replacement of CXD2663GA (IC601) used in this set requires a special tool. Therefore, it cannot be replaced.

Flexible Circuit Board Repairing

- Keep the temperature of the soldering iron around 270 °C during repairing.
- Do not touch the soldering iron on the same conductor of the circuit board (within 3 times).
- Be careful not to apply force on the conductor when soldering or unsoldering.

Notes on chip component replacement

- Never reuse a disconnected chip component.
- Notice that the minus side of a tantalum capacitor may be damaged by heat.

CAUTION

Use of controls or adjustments or performance of procedures other than those specified herein may result in hazardous radiation exposure.

CLASS 1 LASER PRODUCT
LUOKAN 1 LASERLAITE
KLASS 1 LASERAPPARAT

This MiniDisc player is classified as a CLASS 1 LASER product.

The CLASS 1 LASER PRODUCT label is located on the bottom exterior.

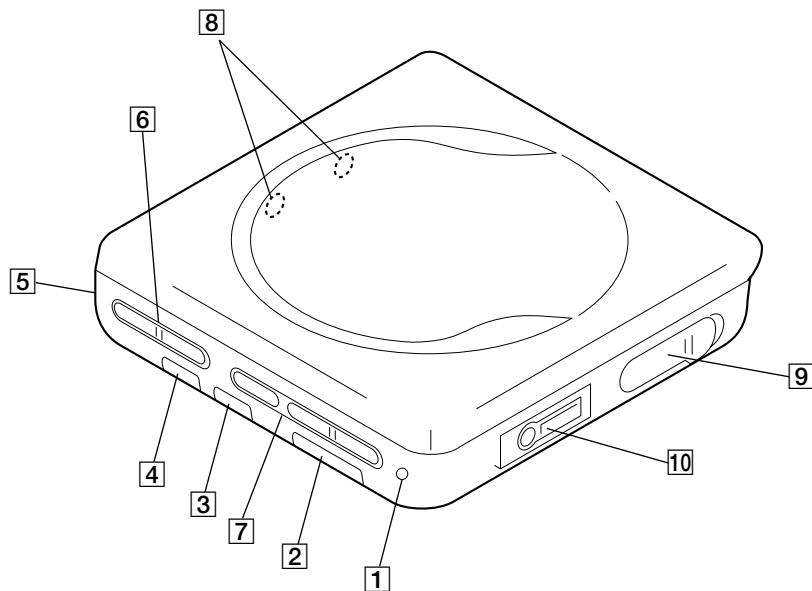
SAFETY-RELATED COMPONENT WARNING!!

COMPONENTS IDENTIFIED BY MARK ▲ OR DOTTED LINE WITH MARK ▲ ON THE SCHEMATIC DIAGRAMS AND IN THE PARTS LIST ARE CRITICAL TO SAFE OPERATION. REPLACE THESE COMPONENTS WITH SONY PARTS WHOSE PART NUMBERS APPEAR AS SHOWN IN THIS MANUAL OR IN SUPPLEMENTS PUBLISHED BY SONY.

SECTION 2 GENERAL

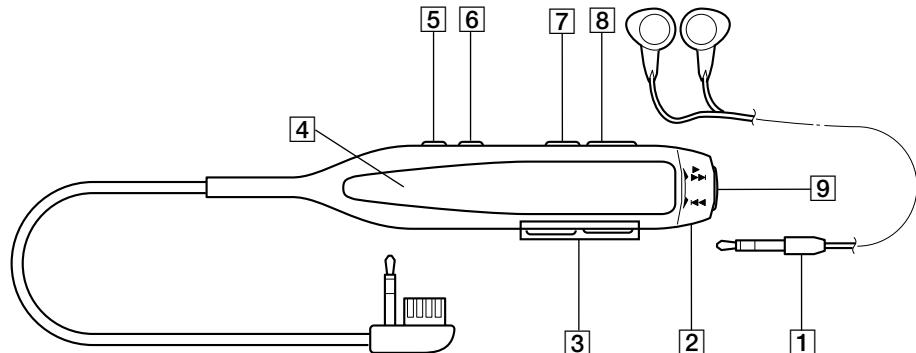
- LOCATION OF CONTROLS

- Main Unit -



- | | |
|-----------------------------|---|
| [1] OPERATE indicator | [7] MD operate buttons
▶▶/▶ (FF • PLAY)
◀◀ (REW)
■ (STOP) |
| [2] HOLD switch | [8] External battery terminal (+/-) |
| [3] DIGITAL MEGABASS switch | [9] OPEN switch |
| [4] AVLS switch | [10] ○ REMOTE jack |
| [5] Battery cover | |
| [6] VOLUME +/- buttons | |

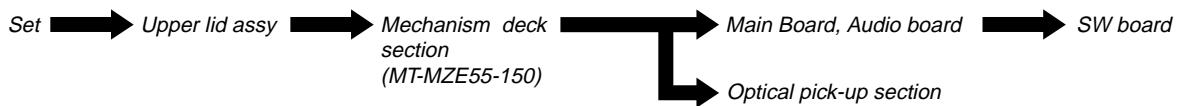
- Remote commander with headphone -



- | |
|---|
| [1] Headphone |
| [2] MD operate switch
▶/▶▶ (PLAY • FF)
◀◀ (REW) |
| [3] VOL +/- buttons |
| [4] Display window |
| [5] DISPLAY button |
| [6] PLAYMODE button |
| [7] II (PAUSE) button |
| [8] HOLD ▶ switch |
| [9] ■ (STOP) button |

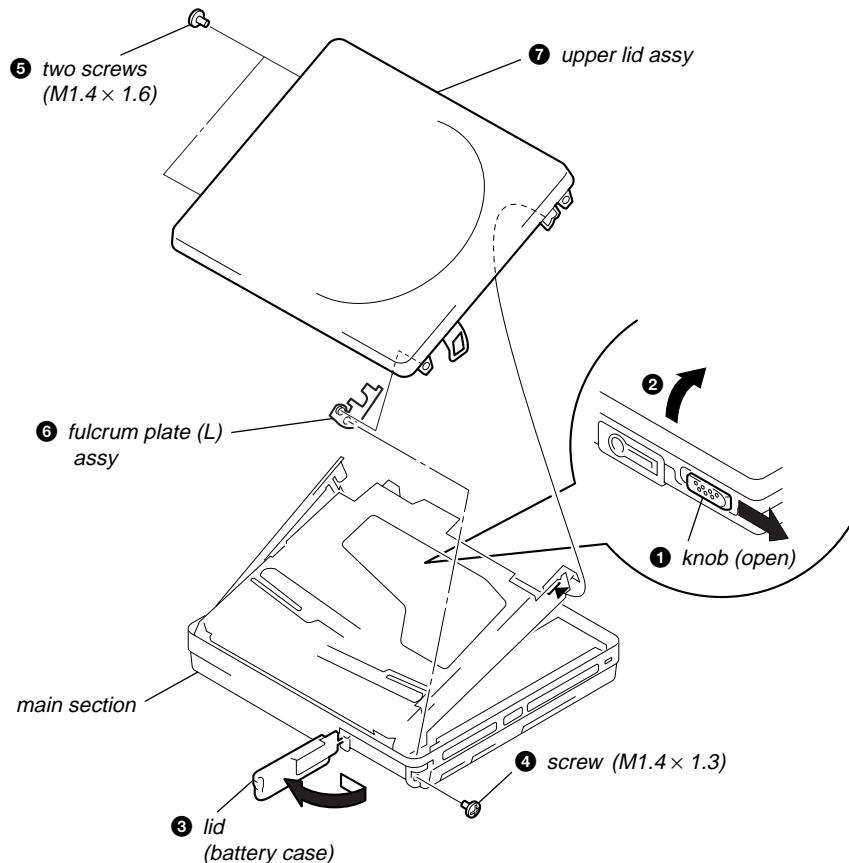
SECTION 3 DISASSEMBLY

- This set can be disassembled in the order shown below.

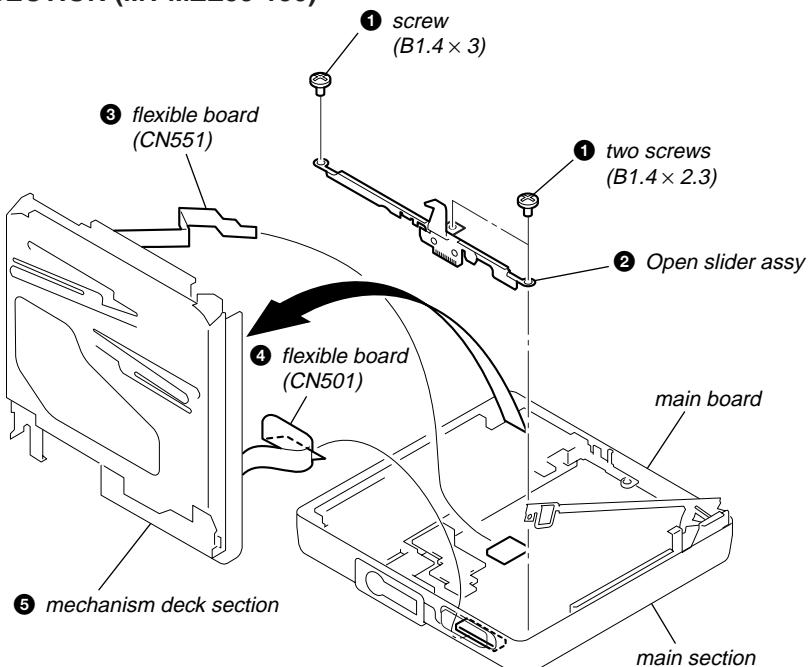


Note: Follow the disassembly procedure in the numerical order given.

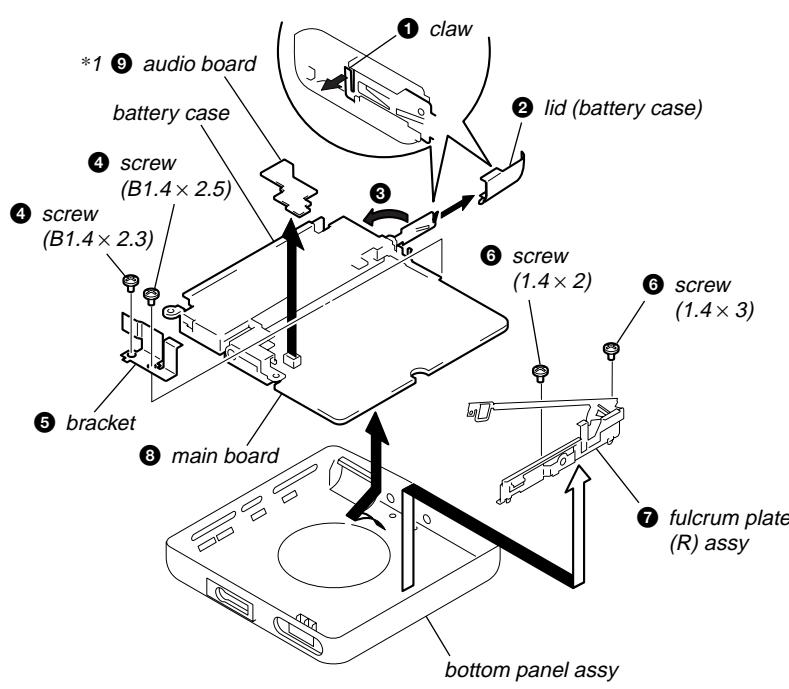
UPPER LID ASSY



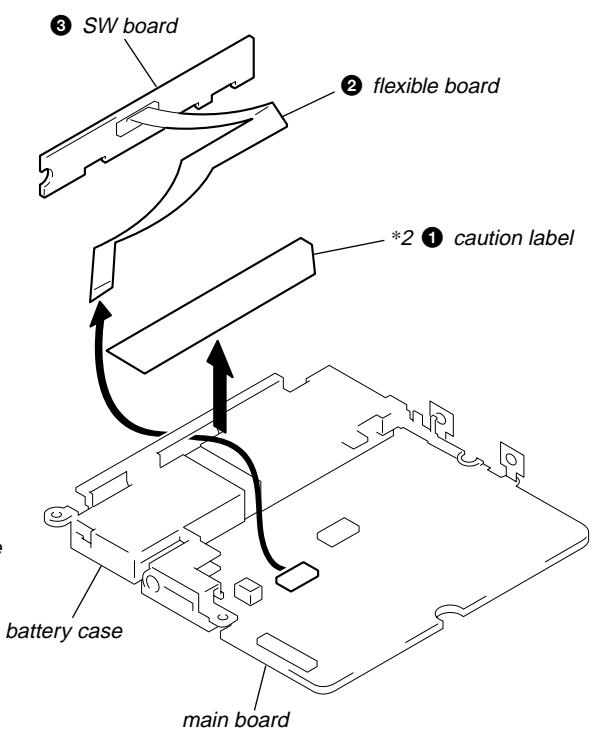
MECHANISM DECK SECTION (MT-MZE55-150)



MAIN BOARD, AUDIO BOARD



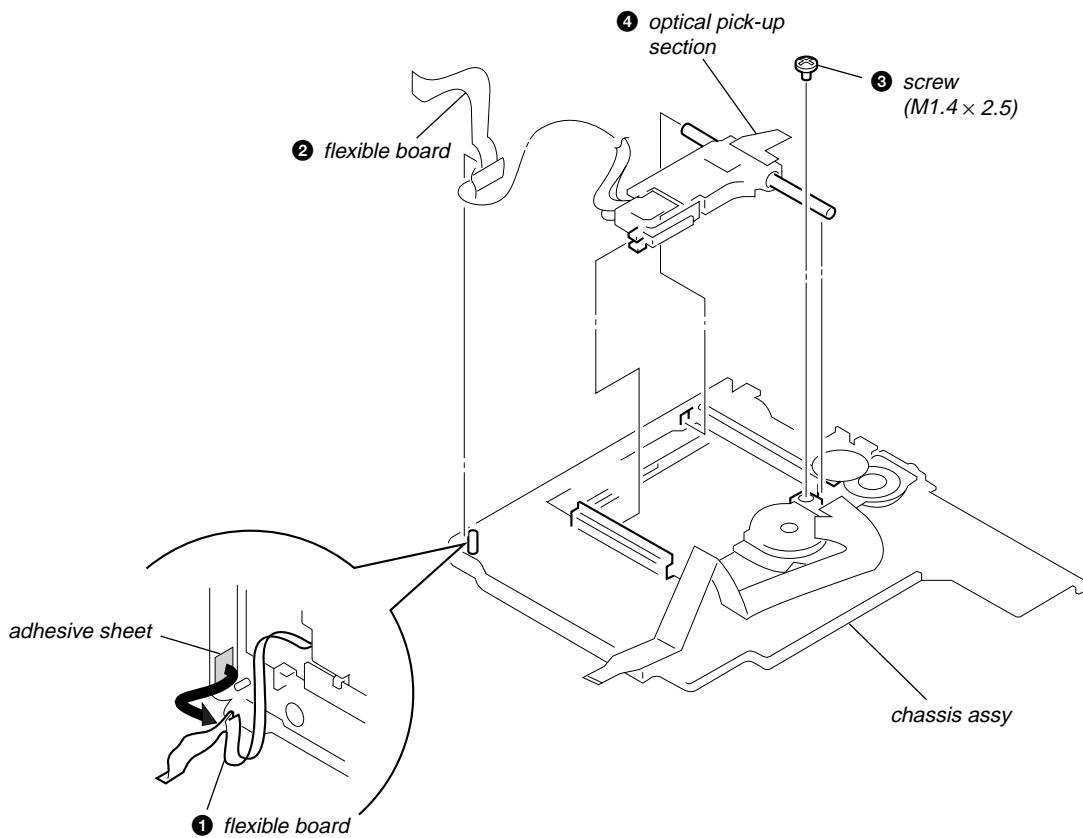
SW BOARD



*1 Note: In removing the Audio board, raise the connector section uprightly.

*2 Note: If the SW board or flexible board is removed, the caution label (4-213-092-01) on the flexible board will be defaced or deformed, and replace it with a new label.

OPTICAL PICK-UP SECTION



SECTION 4 TEST MODE

Outline

- In this set, overall adjustment mode is made available by entering test mode to perform automatic adjustment of CD and MO. In the overall adjustment mode, the disc is determined whether it is CD or MO and adjustments are performed in sequence. If a fault is found, the location of the fault is displayed. Also, in servo mode, each adjustment can be automatically made.
- Operation in the test mode is performed with the remote commander. A key having no particular description in the text, indicates a remote commander key.

Setting the Test Mode

To enter the test mode, two methods are available :

- Entering method with key input.

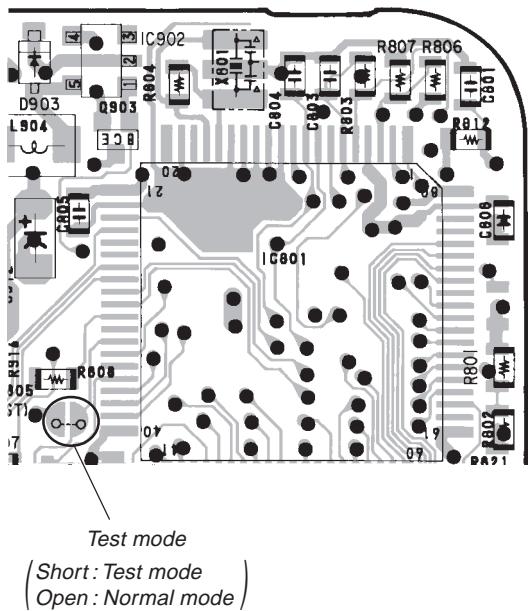
Turn on the HOLD switch on the set. While pressing the ■ key on the set, press the following remote commander keys in the following order :

►/►►| → ►/►►| → |◀| → |◀| → ►/►►| → |◀| →
►/►►| → |◀| → |II| → |II|

- Entering method by shorting the test point

Solder bridge the test point TAP805 (TEST) on the MAIN board (connect IC801 pin ⑬ to GND), and turn on the power.

- MAIN BOARD (Conductor side) -



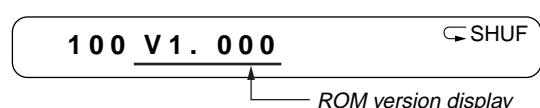
Releasing the Test Mode

A test mode releasing method varies depending on the test mode setting method.

- When test mode was entered with key input, turn off the power.
- When test mode was entered by shorting the test point, turn off the power and open the solder bridge of TAP805 (TEST MODE) on the MAIN board.

Operation of Setting on Test Mode

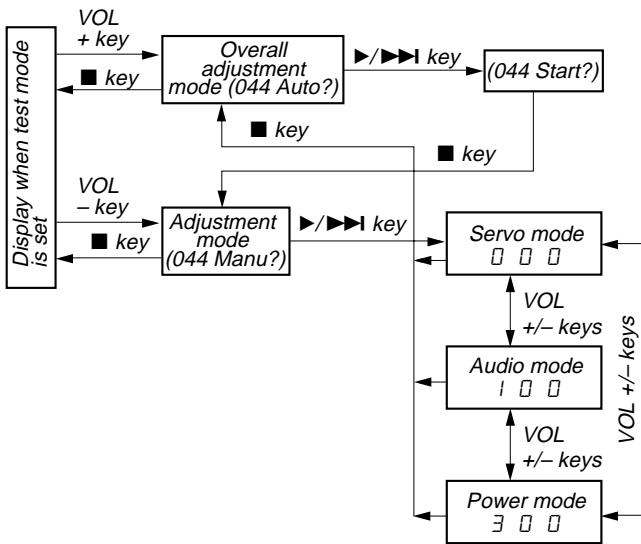
When the test mode is set, the LCD displays the following :



- The cycle - the above ROM version display → All lit → All off - is repeated.
- When the PLAYMODE key is pressed and hold down, the display at that time is held so that display can be checked.

Configuration of Test Mode

The test mode has the configuration given below.

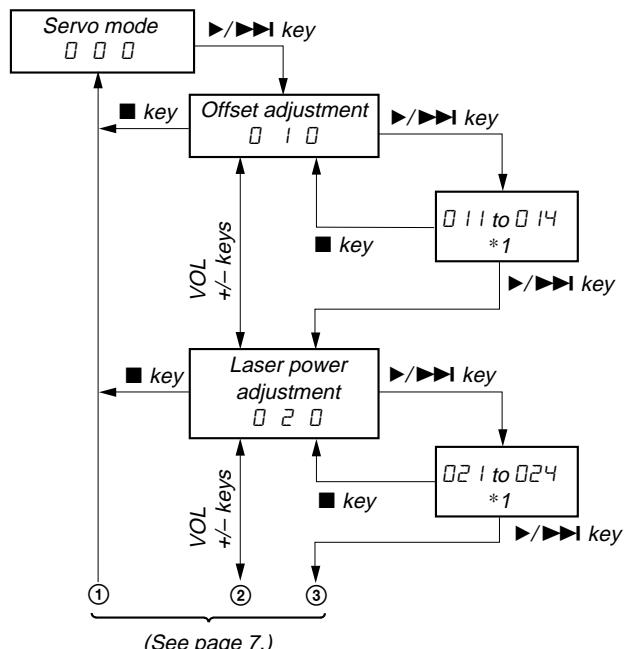


Displays of the LCD on the remote commander are shown in parenthesis.

Servo Mode

- Set the test mode, press the VOL – key and use the ►/►►| key to set the servo mode.
- When the servo mode is set, use the ►►|/► key and the |◀| key on the set to move the optical pick-up to the outer circumference and to the inner circumference respectively.
- When entering another mode, refer to the configuration of test mode.

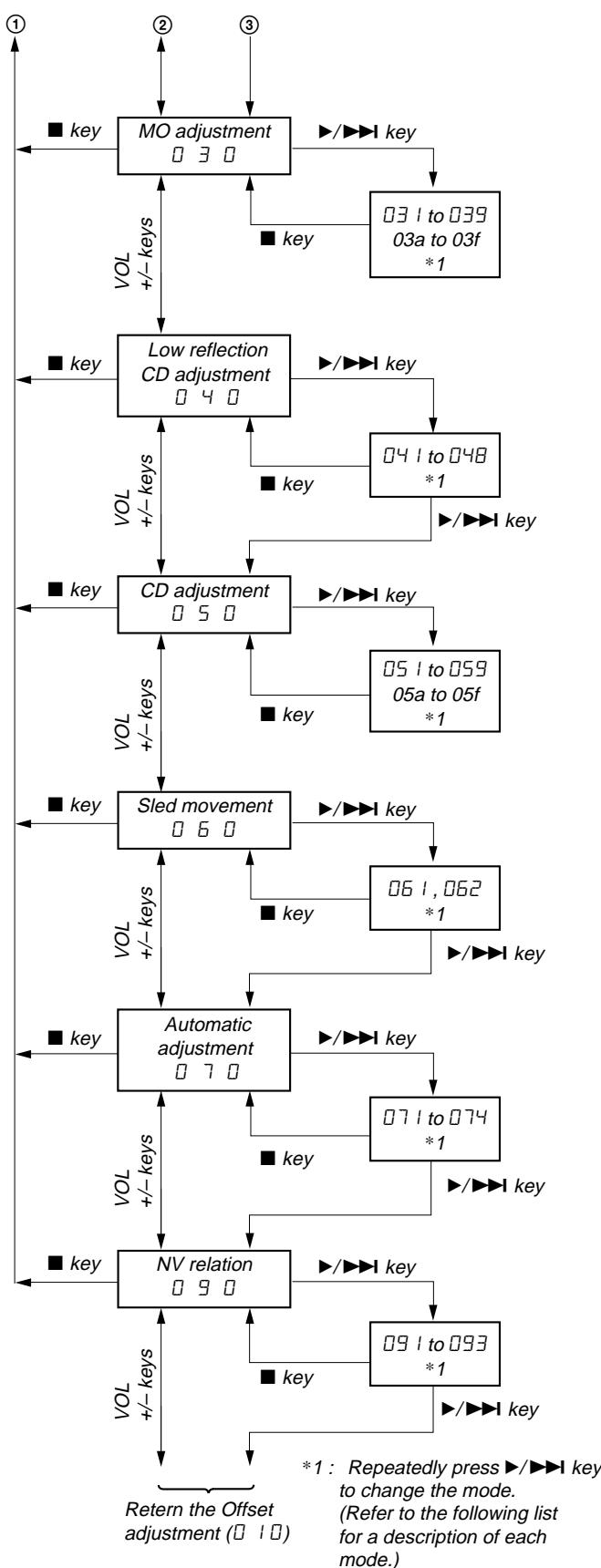
1. Structure of Servo Mode



(See page 7.)

*1 Repeatedly press ►/►►| key to change the mode.
(Refer to the following list for a description of each mode.)

(See page 6.)



2. Description of Each Mode

010 Offset adjustment

Mode	Description
011	VC offset, FE offset, ABCD offset
012	Not used
013	Not used
014	Not used

020 Laser power adjustment

Mode	Description
021	MO power (GRV)
022	MO power (LPIT)
023	CD power (HPIT)
024	Not used

030 MO adjustment

Mode	Description
031	MO EF balance
032	MO tracking offset
033	MO ABCD gain
034	MO focus gain
035	MO tracking gain
036	MO focus bias
037	_____
038	_____
039	_____
(03a)	_____
(03b)	_____
(03c)	_____
(03d)	Not used
(03e)	Not used
(03f)	Not used

040 Lower reflection CD adjustment

Mode	Description
041	Lower reflection CD EF balance
042	Lower reflection CD tracking offset
043	Lower reflection CD ABCD gain
044	Lower reflection CD focus gain
045	Lower reflection CD tracking gain
046	Lower reflection CD focus bias
047	_____
048	Not used

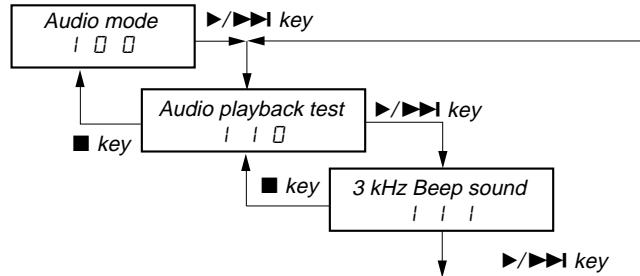
050 CD adjustment

Mode	Description
051	CD EF balance
052	CD tracking offset
053	CD ABCD gain
054	CD focus gain
055	CD tracking gain
056	CD focus bias
057	_____
058	_____
059	_____
(05a)	_____
(05b)	_____
(05c)	_____
(05d)	Not used
(05e)	Not used
(05f)	Not used

Audio Mode

- Enter the test mode and press the VOL – key. Then, press the ▶/▶▶ key and the VOL + key in this turn to enter audio mode.
- When entering another mode, refer to the configuration of test mode.

1. Structure of Audio Mode



060 Sled movement

Mode	Description
061	Sled in
062	Sled out

070 Automatic adjustment

Mode	Description
071	Focus search
072	Access 32
073	Not used
074	Not used

090 NV relation

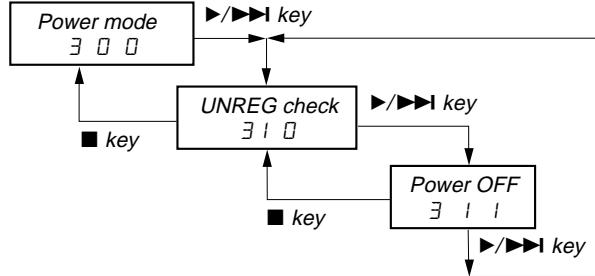
Mode	Description
091	NV clear
092	Power OFF
093	Function code change

Note: The parenthesizal mode numbers in table are not displayed on the LCD of remote commander.

Power Mode

- Enter the test mode and press the VOL – key. Then, press the ▶/▶▶ key and the VOL – key in this turn to enter power mode.
- When entering another mode, refer to the configuration of test mode.

1. Structure of Power Mode

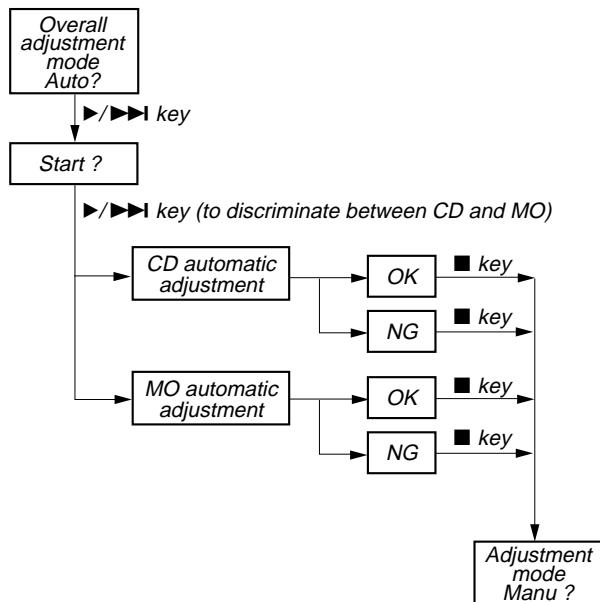


Overall Adjustment Mode

- Enter the test mode and press the VOL + key to enter overall adjustment mode.
- When entering another mode, refer to the configuration of test mode.
- When the overall adjustment mode is entered, the LCD on the remote commander display the following :

044 Auto?

1. Structure of Overall Adjustment Mode



SECTION 5

ELECTRICAL ADJUSTMENTS

Notes for Adjustment

- In this set, automatic adjustment of CD and MO can be performed by entering the test mode. (See page 6)
- Adjustments are performed in the overall adjustment mode. If an item is determined as NG, the item is readjusted in servo mode.

Adjustment Method in Overall Adjustment Mode

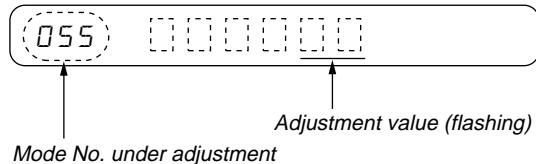
1. Enter the test mode and press the VOL + key to enter overall adjustment mode.
 2. Insert the CD test disc TDYS-1 (Parts No. 4-963-646-01) or SONY MO disc (recorded) commercially available.
 3. Press the ▶/▶▶ key. The disc is determined whether it is CD or MO and each adjustment mode is set. Automatic adjustments are performed in the order of the items listed below.
- In CD Automatic adjustment Mode

No.	Mode	Description
1	061	Sled in
2	062	Sled out
3	071	Focus search
4	051	CD EF balance
5	053	CD ABCD gain
6	051	CD EF balance
7	052	CD tracking offset
8	054	CD focus gain
9	055	CD tracking gain
10	056	CD focus bias

- In MO Automatic adjustment Mode

No.	Mode	Description
1	061	Sled in
2	062	Sled out
3	071	Focus search
4	031	MO EF balance
5	033	MO ABCD gain
6	031	MO EF balance
7	032	MO tracking offset
8	034	MO focus gain
9	035	MO tracking gain
10	036	MO focus bias

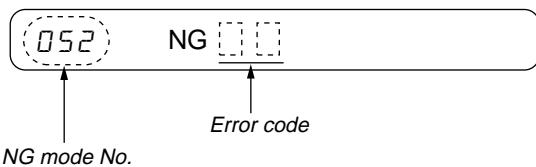
* Remote commander display during automatic adjustment



4. If result of automatic adjustment is OK, the following display appears.



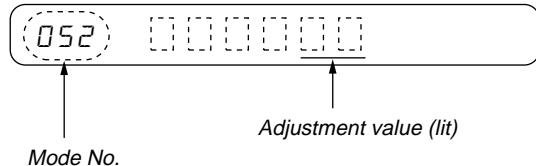
5. If result of automatic adjustment is NG, the following display appears.



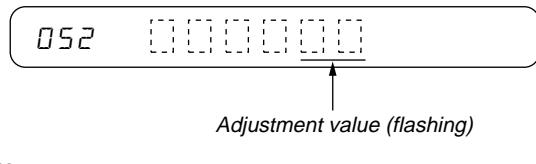
* If NG, enter servo mode to perform automatic adjustment of the item determined as NG.

Adjustment in Servo Mode Method

1. When each adjustment mode is set according to the structure of servo mode, the lower two digits of the mode No. and the adjustment value written in EEPROM are displayed and lit on the LCD on the remote commander. (See page 6)

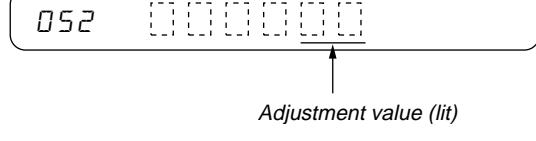


2. When the ▯ key is pressed, the following display appears and the automatic adjustment is performed.



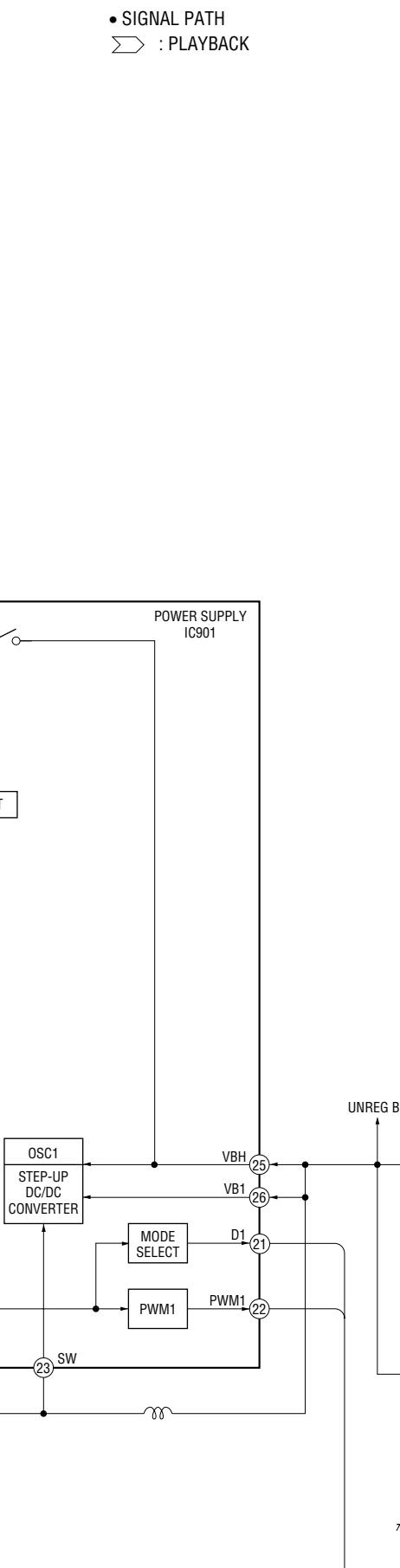
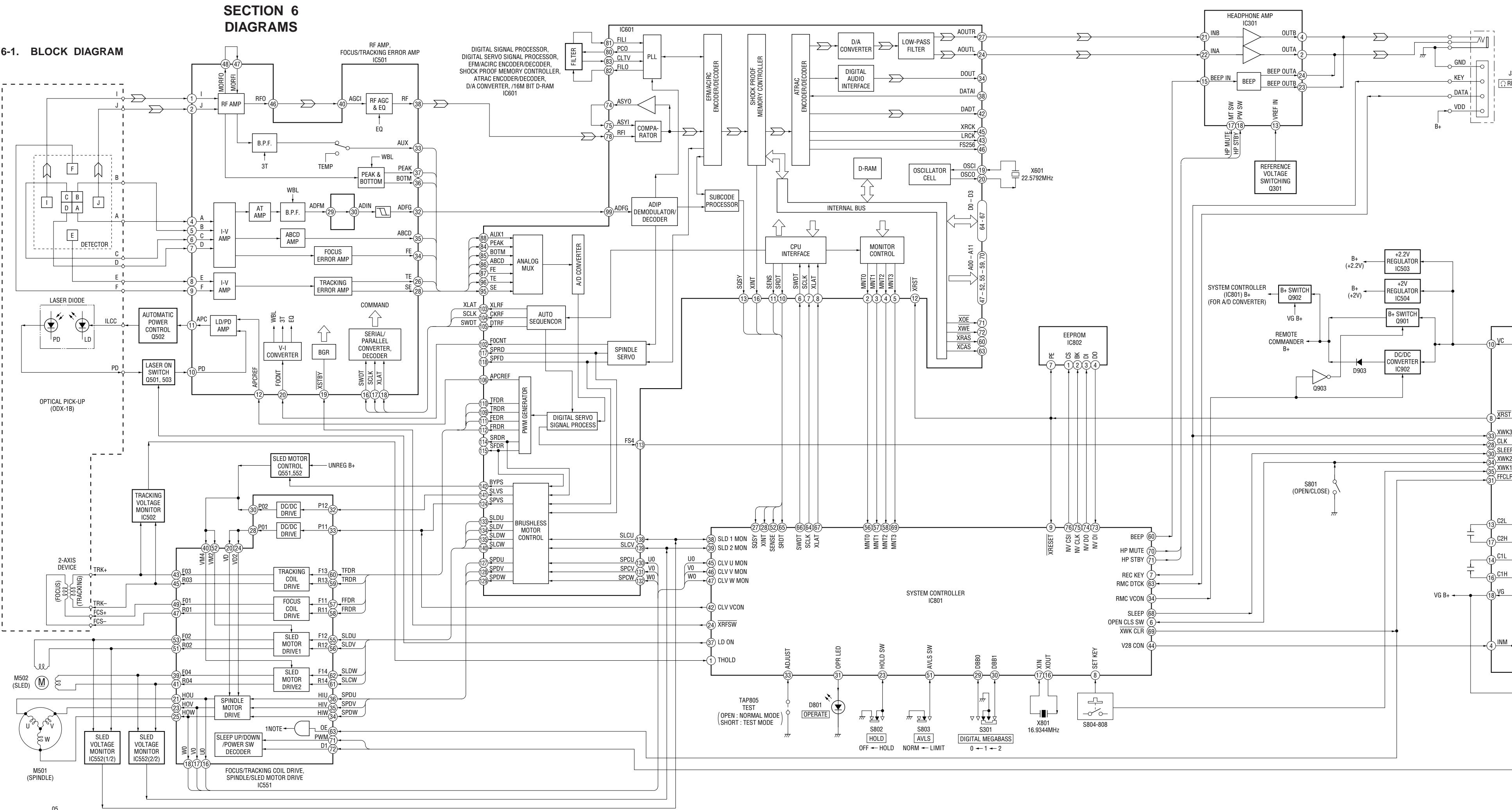
Note: Although the VOL +/- keys can be used to change the adjustment value to any value, they should not be used whenever possible.

3. When the automatic adjustment is completed, the flashing adjustment value is lit.



SECTION 6 DIAGRAMS

6-1. BLOCK DIAGRAM



6-2. PRINTED WIRING BOARDS

Note on Printed Wiring Boards:

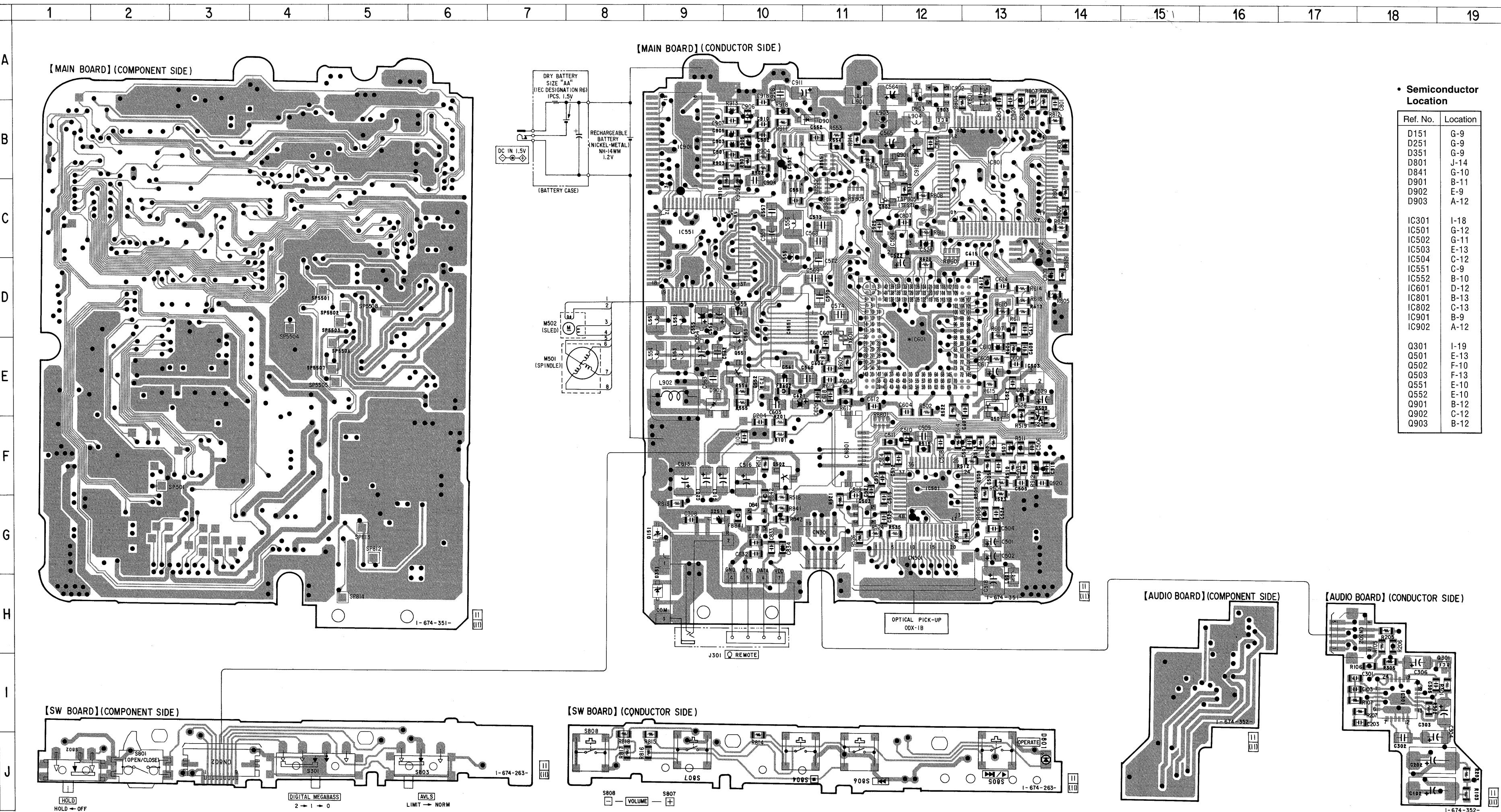
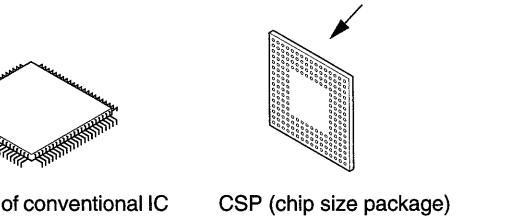
- : parts extracted from the conductor side.
- : Through hole.
- △ : internal component.
- : Pattern from the side which enables seeing.
(The other layers' patterns are not indicated.)

Caution:
Pattern face side: Parts on the pattern face side seen from
(Conductor Side) the pattern face are indicated.
Parts face side: Parts on the parts face side seen from
(Component Side) the parts face are indicated.

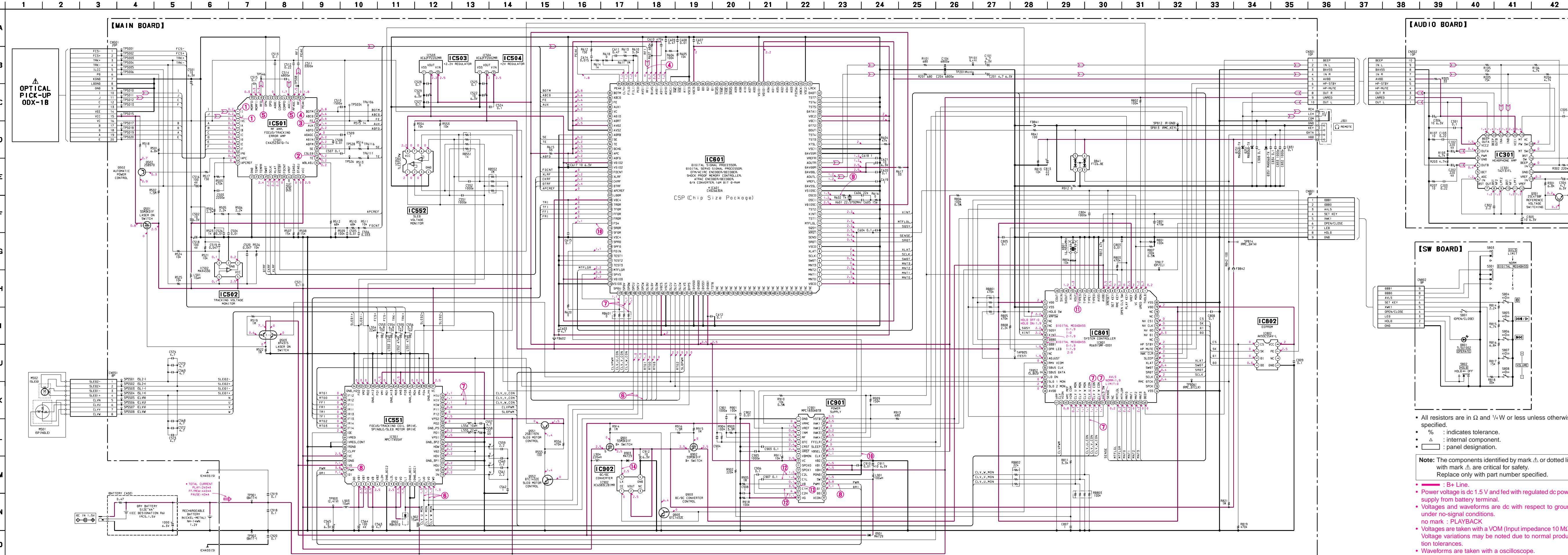
- Main board is four-layer printed board.
However, the patterns of layers 2 and 3 have not been included in this diagrams.

* IC601 is not replaceable

- Lead Layouts



6-3. SCHEMATIC DIAGRAM • See page 23 for Waveforms. • See page 24 for IC Block Diagrams.



* IC601 is not replaceable

Note on Schematic Diagram:

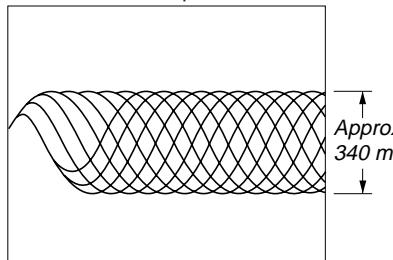
- The voltage and waveform of CSP (chip size package) cannot be measured, because its lead layout is different from that of conventional IC.

Note: The components identified by mark △ or dotted line with mark △ are critical for safety.
Replace only with part number specified.

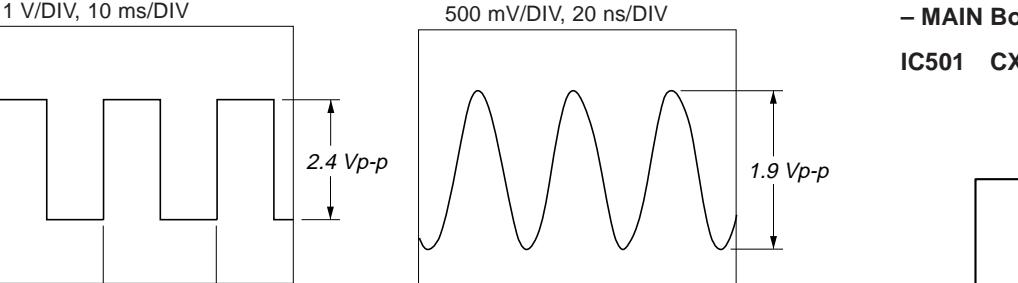
- : B+ Line.
- Power voltage is dc 1.5 V and fed with regulated dc power supply from battery terminal.
- Voltages and waveforms are dc with respect to ground under no-signal conditions.
no mark : PLAYBACK
- Voltages are taken with a VOM (Input impedance 10 MΩ). Voltage variations may be noted due to normal production tolerances.
- Waveforms are taken with an oscilloscope. Voltage variations may be noted due to normal production tolerances.
- Circled numbers refer to waveforms.
- Signal path.
- △ : PLAYBACK

• Waveforms
- MAIN Board -

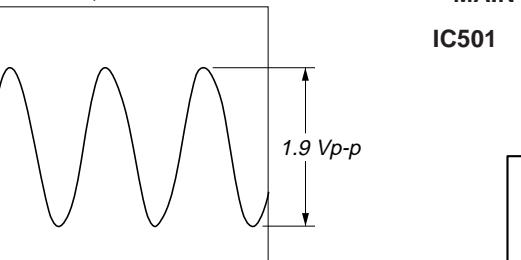
① IC501 ①, ② (I,J)
100 mV/DIV, 5 μ s/DIV



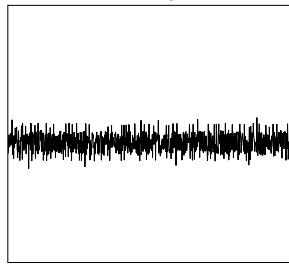
⑥ IC551 ⑯, ⑰, ⑱ (U0, V0, W0)
IC601 ⑯, ⑰, ⑱ (SPCU, SPCV, SPCW)
1 V/DIV, 10 ms/DIV



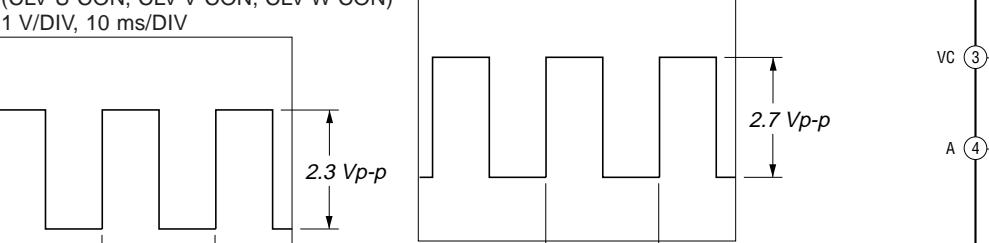
⑪ IC801 ⑯ (XOUT)
500 mV/DIV, 20 ns/DIV



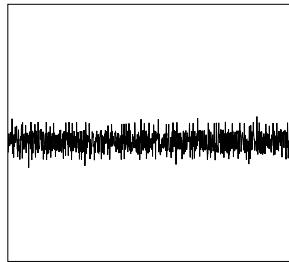
② IC501 ⑯ (TE)
10 mV/DIV, 1 μ s/DIV



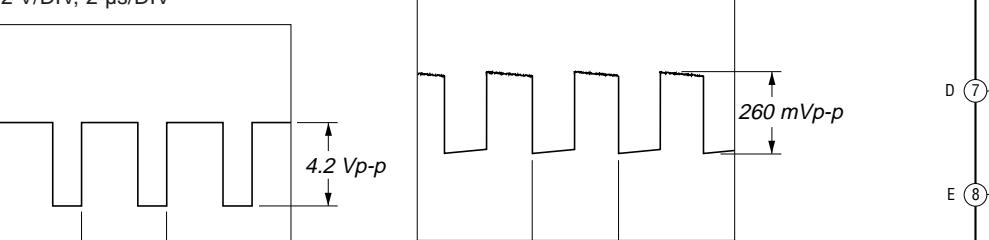
⑦ IC551 ⑯, ⑰, ⑱ (HIW, HIV, HIU)
IC601 ⑯, ⑰, ⑱ (SPDU, SPDV, SPDW)
IC801 ⑯, ⑰, ⑱ (CLV U CON, CLV V CON, CLV W CON)
1 V/DIV, 10 ms/DIV



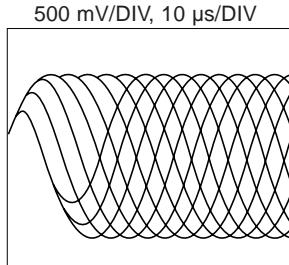
③ IC501 ⑯ (FE)
100 mV/DIV, 1 μ s/DIV



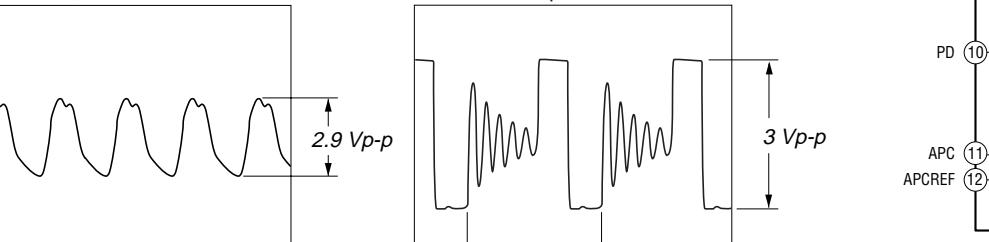
⑩ IC551 ⑯ (PWM), IC901 ⑯ (PWM1)
2 V/DIV, 2 μ s/DIV



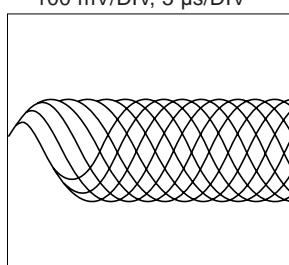
④ IC501 ⑯ (RF), IC601 ⑯ (RF1)
500 mV/DIV, 10 μ s/DIV



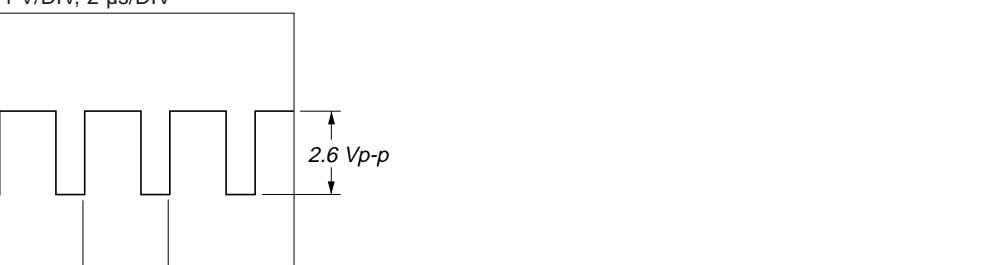
⑨ IC601 ⑯ (OSCO)
1 V/DIV, 20 ns/DIV



⑤ IC501 ⑯, ⑯ (AGCI, RFO)
100 mV/DIV, 5 μ s/DIV

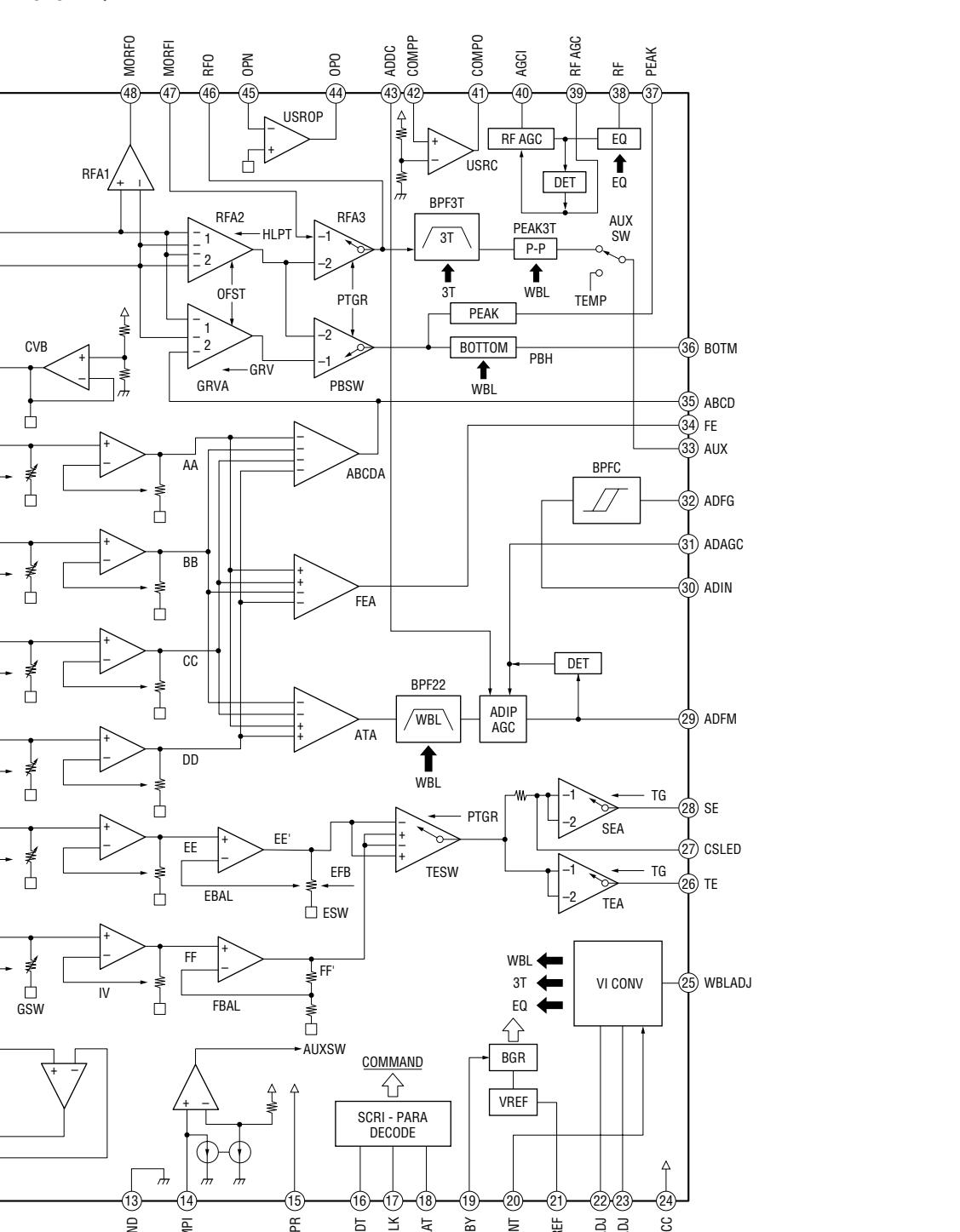


⑩ IC601 ⑯ (FS4), IC901 ⑯ (CLK)
1 V/DIV, 2 μ s/DIV

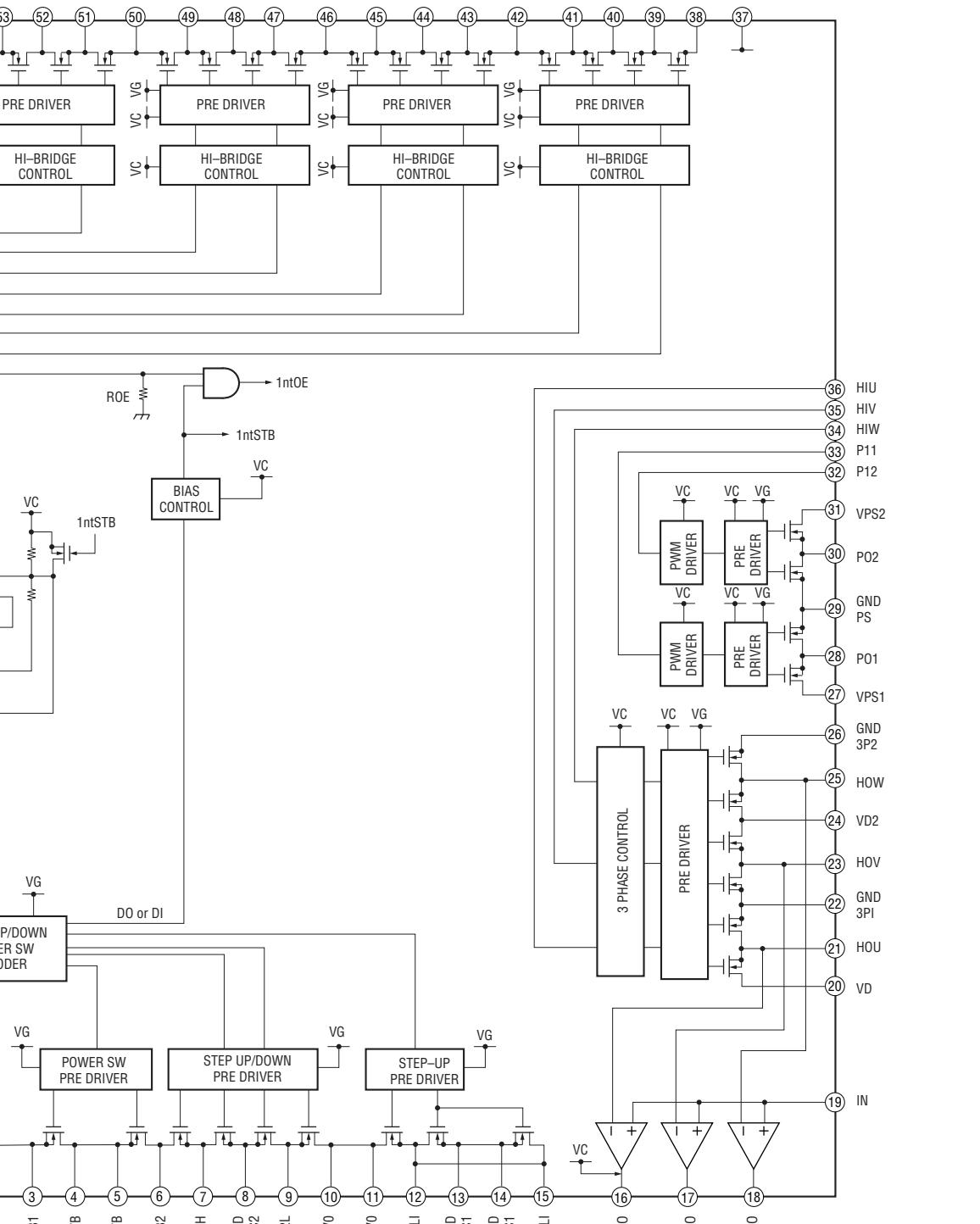


• IC Block Diagrams
- MAIN Board -

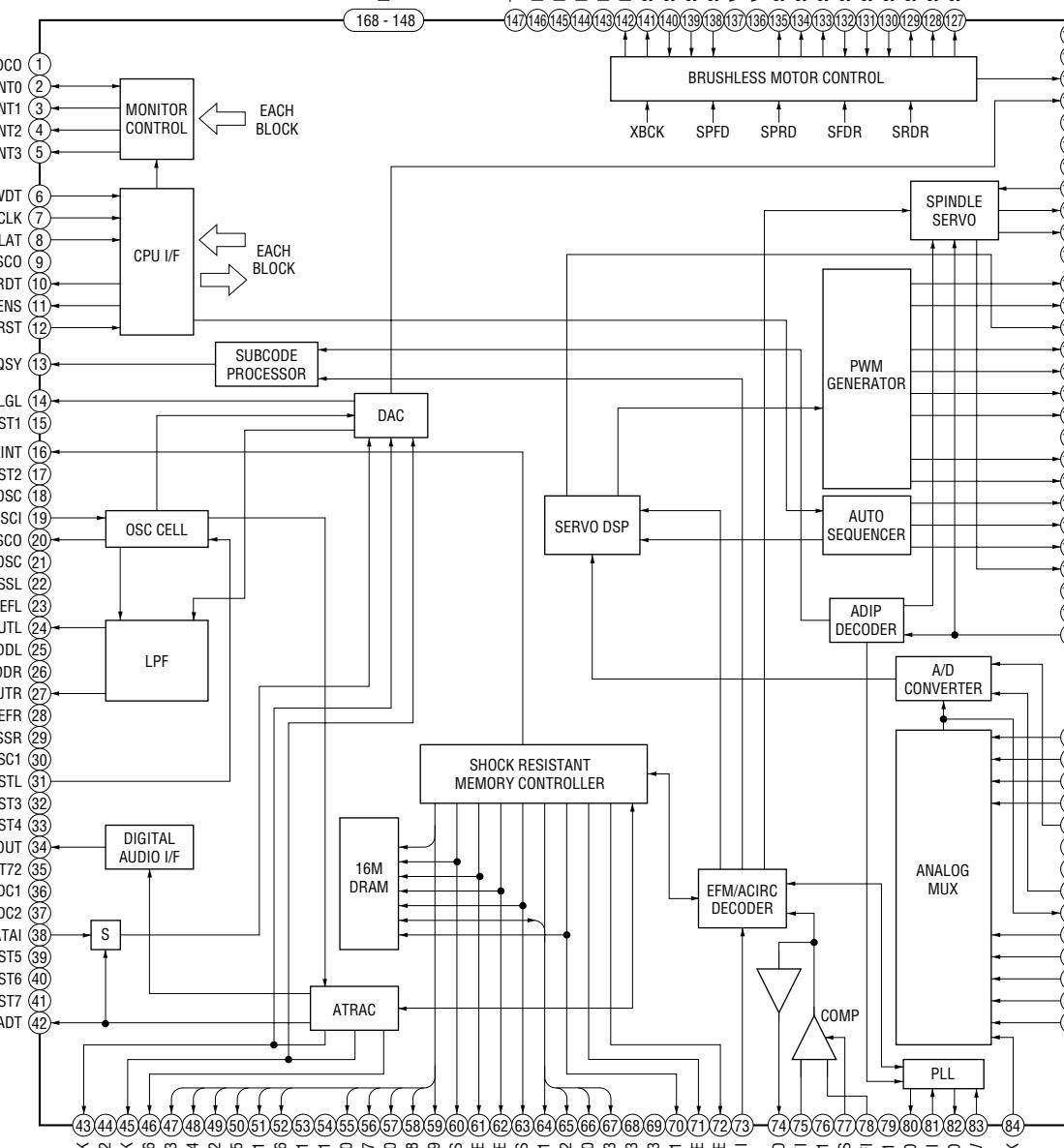
IC501 CXA2523ATQ-T4



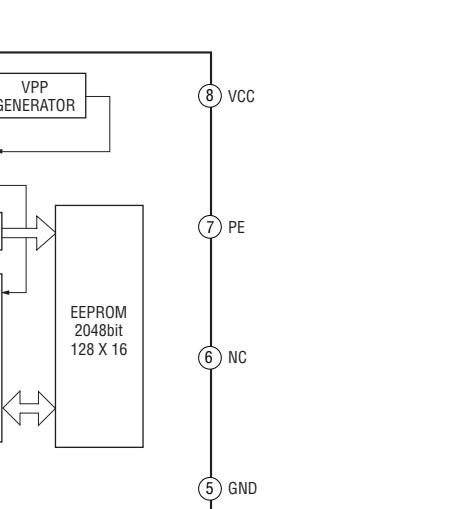
IC551 MPC17A55FTA



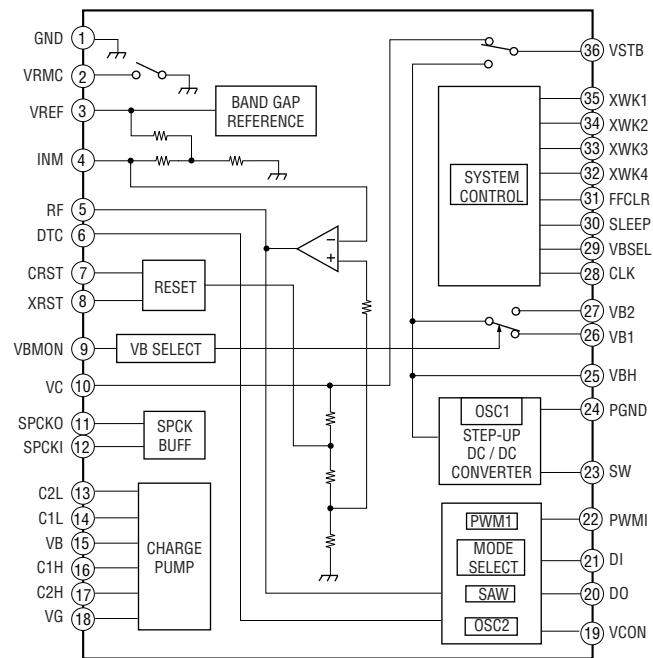
IC601 CXD2663GA



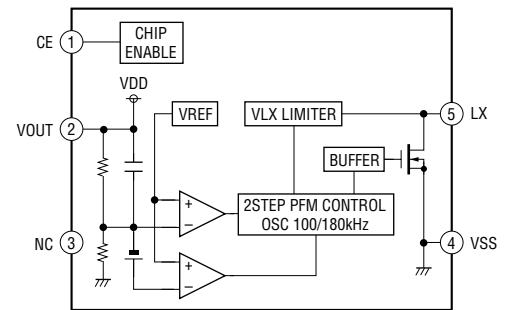
IC802 AK93C55AV-L



IC901 MPC1830ADTB

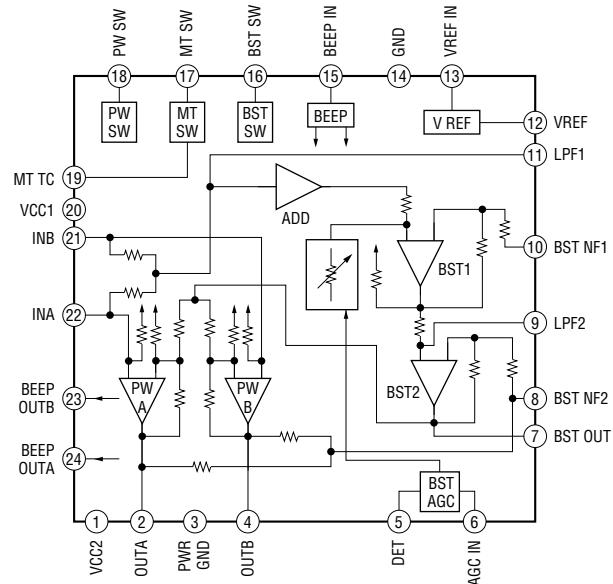


IC902 XC6383C281MR



- AUDIO Board -

IC301 TA2131FL (EL)



6-4. IC PIN FUNCTION DESCRIPTION

• MAIN BOARD IC501 CXA2523ATQ-T4 (RF AMP, FOCUS/TRACKING ERROR AMP)

Pin No.	Pin Name	I/O	Description
1	I	I	I-V converted RF signal I input from the optical pick-up block detector
2	J	I	I-V converted RF signal J input from the optical pick-up block detector
3	VC	O	Middle point voltage (+1.2V) generation output terminal
4 to 9	A to F	I	Signal input from the optical pick-up detector (A to F)
10	PD	I	Light amount monitor input from the optical pick-up block laser diode
11	APC	O	Laser amplifier output terminal to the automatic power control circuit
12	APCREF	I	Reference voltage input terminal for setting laser power
13	GND	—	Ground terminal
14	TEMPI	I	Connected to the temperature sensor Not used (open)
15	TEMPR	O	Output terminal for a temperature sensor reference voltage Not used (open)
16	SWDT	I	Writing data input from the CXD2663GA (IC601)
17	SCLK	I	Serial clock signal input from the CXD2663GA (IC601)
18	XLAT	I	Serial latch signal input from the CXD2663GA (IC601)
19	XSTBY	I	Standby control signal input from the system controller (IC801) “L”: standby
20	FOCNT	I	Center frequency control signal input terminal of internal circuit (BPF22, BPF3T, EQ) input from the CXD2663GA (IC601)
21	VREF	O	Reference voltage output terminal Not used (open)
22	EQADJ	I	Center frequency setting terminal for the internal circuit (EQ)
23	3TADJ	I	Center frequency setting terminal for the internal circuit (BPF3T)
24	VCC	—	Power supply terminal (+2.4V)
25	WBLADJ	I	Center frequency setting terminal for the internal circuit (BPF22)
26	TE	O	Tracking error signal output to the CXD2663GA (IC601)
27	CSLED	I	Connected to the capacitor for low-pass filter of the sled error signal
28	SE	O	Sled error signal output to the CXD2663GA (IC601)
29	ADFM	O	FM signal output terminal of the ADIP
30	ADIN	I	Receives a ADIP FM signal in AC coupling
31	ADAGC	I	Connected to the external capacitor for ADIP AGC
32	ADFG	O	ADIP duplex FM signal ($22.05\text{ kHz} \pm 1\text{ kHz}$) output to the CXD2663GA (IC601)
33	AUX	O	Auxiliary signal (I_3 signal/temperature signal) output to the CXD2663GA (IC601)
34	FE	O	Focus error signal output to the CXD2663GA (IC601)
35	ABCD	O	Light amount signal output to the CXD2663GA (IC601)
36	BOTM	O	Light amount signal (RF/ABCD) bottom hold output to the CXD2663GA (IC601)
37	PEAK	O	Light amount signal (RF/ABCD) peak hold output to the CXD2663GA (IC601)
38	RF	O	Playback EFM RF signal output to the CXD2663GA (IC601)
39	RFAGC	I	Connected to the external capacitor for RF auto gain control circuit
40	AGCI	I	Receives a RF signal in AC coupling
41	COMPO	O	User comparator output terminal Not used (open)
42	COMPP	I	User comparator input terminal Not used (fixed at “L”)
43	ADD	I	Connected to the external capacitor for cutting the low band of the ADIP amplifier
44	OPO	O	User operational amplifier output terminal Not used (open)
45	OPN	I	User operational amplifier inversion input terminal Not used (fixed at “L”)
46	RFO	O	RF signal output terminal
47	MORFI	I	Receives a MO RF signal in AC coupling
48	MORFO	O	MO RF signal output terminal

• MAIN BOARD IC601 CXD2663GA

(DIGITAL SIGNAL PROCESSOR, DIGITAL SERVO SIGNAL PROCESSOR, EFM/ACIRC ENCODER/DECODER,
SHOCK PROOF MEMORY CONTROLLER, ATRAC ENCODER/DECODER, D/A CONVERTER, 16M BIT D-RAM)

Pin No.	Pin Name	I/O	Description
1	VDCO	—	Power supply terminal (+2V) (for internal logic)
2	MNT0	O	Signal indicating the speed follow-up spinning mode output to the system controller (IC801) “H”: speed follow-up spinning mode
3	MNT1	O	Sled motor operation monitor signal output to the system controller (IC801) “H”: monitor drive
4	MNT2	O	Speed limiter signal output to the system controller (IC801) “L”: limiter on
5	MNT3	O	Window signal to detect an inverse trigger edge output to the system controller (IC801) “H”: edge detectable
6	SWDT	I	Writing data input from the system controller (IC801)
7	SCLK	I	Serial clock signal input from the system controller (IC801)
8	XLAT	I	Serial data latch pulse input from the system controller (IC801)
9	VSCO	—	Ground terminal (for internal logic)
10	SRDT	O	Reading data output to the system controller (IC801)
11	SENS	O	Internal status (SENSE) output to the system controller (IC801)
12	<u>XRST</u>	I	System reset signal input from the MPC1830ADTB (IC901) “L”: reset For several hundreds msec. after the power supply rises, “L” is input, then it changes to “H”
13	SQSY	O	Subcode Q sync (SCOR) output to the system controller (IC801) “L”: is output every 13.3 msec Almost all, “H” is output
14	MTFLGL	O	Muting applied to analog signal input in non-signal status causes the signal to be “H” automatically Not used
15	TST1	I	Input terminal for the test (fixed at “L”)
16	XINT	O	Interrupt status output to the system controller (IC801)
17	TST2	I	Input terminal for the test (fixed at “L”)
18	VDIOSC	—	Power supply terminal (+2.4V) (for oscillator cell)
19	OSCI	I	System clock (512Fs=22.5792 MHz) input terminal
20	OSCO	O	System clock (512Fs=22.5792 MHz) output terminal
21	VSIOSC	—	Ground terminal (for oscillator cell)
22	DAVSSL	—	Ground terminal (for internal D/A converter L-ch)
23	VREFL	O	Reference voltage output terminal (for internal D/A converter L-ch)
24	AOUTL	O	Playback analog signal (L) output to the headphone amplifier (IC301)
25	DAVDDL	—	Power supply terminal (+2.4V) (for internal D/A converter L-ch)
26	DAVDDR	—	Power supply terminal (+2.4V) (for internal D/A converter R-ch)
27	AOUTR	O	Playback analog signal (R) output to the headphone amplifier (IC301)
28	VREFR	O	Reference voltage output terminal (for internal D/A converter R-ch)
29	DAVSSR	—	Ground terminal (for internal D/A converter R-ch)
30	VSC1	—	Ground terminal (for internal logic)
31	XTSL	I	Input terminal for the system clock frequency setting “L”: 45.1584 MHz, “H”: 22.5792 MHz (fixed at “H” in this set)
32, 33	TST3, TST4	I	Input terminal for the test (normally : fixed at “L”)
34	DOUT	O	Digital audio signal output terminal when playback mode Not used (open)
35	DT72	O	Not used (open)
36, 37	VDC1, VDC2	—	Power supply terminal (+2V) (for internal logic)
38	DATAI	I	Input terminal of external audio data to the internal D/A converter Not used (open)
39 to 41	TST5 to TST7	I	Input terminal for the test (normally : fixed at “L”)
42	DADT	O	Playback data signal output to the external D/A converter Not used (open)

Pin No.	Pin Name	I/O	Description
43	LRCK	O	L/R sampling clock signal (44.1 kHz) output to the external D/A converter Not used (open)
44	VSC2	—	Ground terminal (for internal logic)
45	XBCK	O	Bit clock signal (2.8224 MHz) output to the external D/A converter Not used (open)
46	FS256	O	Clock signal (11.2896 MHz) output to the external D/A converter Not used (open)
47 to 52	A03, A04, A02, A05, A01, A06	O	Address signal output to the external D-RAM Not used (open)
53	VDIO1	—	Power supply terminal (+2.2V) (for I/O cell)
54	VSIO1	—	Ground terminal (for I/O cell)
55 to 59	A00, A07, A10, A08, A09	O	Address signal output to the external D-RAM Not used (open)
60	<u>XRAS</u>	O	Row address strobe signal output to the external D-RAM “L” active Not used (open)
61	<u>IXOE</u>	O	Output enable signal output terminal “L” active Not used (open)
62	<u>IXWE</u>	O	Data write enable signal output terminal “L” active Not used (open)
63	<u>XCAS</u>	O	Column address strobe signal output to the external D-RAM “L” active Not used (open)
64 to 67	D1, D2, D0, D3	I/O	Two-way data bus with the external D-RAM Not used (open)
68	VDC3	—	Power supply terminal (+2V) (for internal logic)
69	VSC3	—	Ground terminal (for internal logic)
70	A11	O	Address signal output to the external D-RAM Not used (open)
71	<u>XOE</u>	O	Output enable signal output to the external D-RAM “L” active Not used (open)
72	<u>XWE</u>	O	Data write enable signal output to the external D-RAM “L” active Not used (open)
73	MVCI	I	Digital in PLL oscillation input from the external VCO Not used (fixed at “L”)
74	ASYO	O	Playback EFM full-swing output terminal
75	ASYI	I	Playback EFM asymmetry comparator voltage input terminal
76	AVD1	—	Power supply terminal (+2.4V) (analog system)
77	BIAS	I	Playback EFM asymmetry circuit constant current input terminal
78	RFI	I	Playback EFM RF signal input from the CXA2523ATQ (IC501)
79	AVS1	—	Ground terminal (analog system)
80	PCO	O	Phase comparison output for master clock of the recording/playback FEM master PLL
81	FILI	I	Filter input for master clock of the recording/playback EFM master PLL
82	FILO	O	Filter output for master clock of the recording/playback EFM master PLL
83	CLTV	I	Internal VCO control voltage input of the recording/playback EFM master PLL
84	PEAK	I	Light amount signal (RF/ABCD) peak hold input from the CXA2523ATQ (IC501)
85	BOTM	I	Light amount signal (RF/ABCD) bottom hold input from the CXA2523ATQ (IC501)
86	ABCD	I	Light amount signal input from the CXA2523ATQ (IC501)
87	FE	I	Focus error signal input from the CXA2523ATQ (IC501)
88	AUX1	I	Auxiliary signal (I_3 signal/temperature signal) input from the CXA2523ATQ (IC501)
89	VC	I	Middle point voltage (+1.2V) input terminal
90	ADIO	O	Monitor output of the A/D converter input signal Not used (open)
91	ADRT	I	A/D converter operational range upper limit voltage input terminal (fixed at “H” in this set)
92	AVD2	—	Power supply terminal (+2.4V) (analog system)
93	AVS2	—	Ground terminal (analog system)
94	ADRB	I	A/D converter operational range lower limit voltage input terminal (fixed at “L” in this set)
95	SE	I	Sled error signal input from the CXA2523ATQ (IC501)
96	TE	I	Tracking error signal input from the CXA2523ATQ (IC501)
97	DCHG	I	Connected to the +2.4V power supply
98	APC	I	Error signal input for the laser automatic power control Not used (fixed at “H”)

Pin No.	Pin Name	I/O	Description
99	ADFG	I	ADIP duplex FM signal ($22.05\text{ kHz} \pm 1\text{ kHz}$) input from the CXA2523ATQ (IC501)
100	VDIO2	—	Power supply terminal (+2.2V) (for I/O cell)
101	VSIO2	—	Ground terminal (for I/O cell)
102	F0CNT	O	Center frequency control signal output terminal of internal circuit (BPF22, BPF3T, EQ) output to the CXA2523ATQ (IC501)
103	XLRF	O	Serial latch signal output to the CXA2523ATQ (IC501)
104	CKRF	O	Serial clock signal output to the CXA2523ATQ (IC501)
105	DTRF	O	Writing data output to the CXA2523ATQ (IC501)
106	APCREF	O	Control signal output to the reference voltage generator circuit for the laser automatic power control
107	LDDR	O	PWM signal output for the laser automatic power control Not used (open)
108	VDC4	—	Power supply terminal (+2V) (for internal logic)
109	TRDR	O	Tracking servo drive PWM signal (−) output to the MPC17A55VF (IC551)
110	TFDR	O	Tracking servo drive PWM signal (+) output to the MPC17A55VF (IC551)
111	FFDR	O	Focus servo drive PWM signal (+) output to the MPC17A55VF (IC551)
112	FRDR	O	Focus servo drive PWM signal (−) output to the MPC17A55VF (IC551)
113	FS4	O	Clock signal (176.4 kHz) output to the MPC1830ADTB (IC901) (X' tal system)
114	SRDR	O	Sled servo drive PWM signal (−) output terminal Not used (open)
115	SFDR	O	Sled servo drive PWM signal (+) output terminal Not used (open)
116	VSC4	—	Ground terminal (for internal logic)
117	SPRD	O	Spindle servo drive PWM signal (−) output terminal Not used (open)
118	SPFD	O	Spindle servo drive PWM signal (+) output terminal Not used (open)
119	FGIN	I	FG signal input terminal for spindle servo
120 to 122	TEST1 to TEST3	I	Input terminal for the test (normally : fixed at “L”)
123	MTFLGR	O	Muting applied to analog signal input in non-signal status causes the signal to be “H” automatically Not used
124	SPVS	O	Spindle servo drive voltage control signal output to the MPC17A55VF (IC551)
125	VDI03	—	Power supply terminal (+2.2V) (for I/O cell)
126	VSI03	—	Ground terminal (for I/O cell)
127	SPDU	O	Spindle servo (U) drive signal output to the MPC17A55VF (IC551)
128	SPDV	O	Spindle servo (V) drive signal output to the MPC17A55VF (IC551)
129	SPDW	O	Spindle servo (W) drive signal output to the MPC17A55VF (IC551)
130	SPCU	I	Spindle servo (U) timing signal input from the MPC17A55VF (IC551)
131	SPCV	I	Spindle servo (V) timing signal input from the MPC17A55VF (IC551)
132	SPCW	I	Spindle servo (W) timing signal input from the MPC17A55VF (IC551)
133	SLDU	O	Sled servo (U) drive signal output to the MPC17A55VF (IC551)
134	SLDV	O	Sled servo (V) drive signal output to the MPC17A55VF (IC551)
135	SLDW	O	Sled servo (W) drive signal output to the MPC17A55VF (IC551)
136	VDC5	—	Power supply terminal (+2V) (for internal logic)
137	VSC5	—	Ground terminal (for internal logic)
138	SLCU	I	Sled servo (U) timing signal input from the MPC17A55VF (IC551)
139	SLCV	I	Sled servo (V) timing signal input from the MPC17A55VF (IC551)
140	SLCW	I	Sled servo (W) timing signal input from the MPC17A55VF (IC551)
141	SLVS	O	Sled servo voltage control signal output to the MPC17A55VF (IC551)
142	BYPS	O	By-pass transistor control signal output terminal for the sled drive power supply
143	DVSS0	—	Ground terminal (for internal 16M bit D-RAM)

Pin No.	Pin Name	I/O	Description
144	DVDD0	—	Power supply terminal (+2.4V) (for internal 16M bit D-RAM)
145	DVSS1	—	Ground terminal (for internal 16M bit D-RAM)
146	DVDD1	—	Power supply terminal (+2.4V) (for internal 16M bit D-RAM)
147	TST8	I	Input terminal for the test Not used (open)
148 to 168	NC	—	Not used (open)

• MAIN BOARD IC801 RU6915MF-0001 (SYSTEM CONTROLLER)

Pin No.	Pin Name	I/O	Description
1	THOLD	I	Two shaft device tracking coil-end voltage monitor input terminal (A/D input)
2	UREG MON	I	Un-regulator power supply voltage monitor input terminal (A/D input)
3	VC MON	I	VC (middle point voltage) power supply voltage monitor input terminal (A/D input)
4	VREF	I	Input terminal for power supply voltage adjustment reference voltage (+2V) (A/D input)
5	PLAY KEY	I	Not used (fixed at "H")
6	OPEN CLS SW	I	Upper panel open/close detect switch (S801) input terminal (A/D input) "L": upper panel close, "H": upper panel open
7	RMC KEY	I	Remote commander with headphone key input terminal (A/D input)
8	SET KEY	I	Set key input terminal (A/D input) S804 to S808 (■, ▶▶ /▶,◀◀, +/-VOLUME keys input)
9	XRESET	I	System reset signal input from the MPC1830ADTB (IC901) "L": reset For several hundreds msec. after the power supply rises, "L" is input, then it changes to "H"
10	AVDD	—	Power supply terminal (+2.4V) (for A/D converter)
11	AVSS	—	Ground terminal (for A/D converter)
12 to15	TYPE0 to TYPE3	I	Setting terminal for model discrimination (bit0 to bit3) Fixed at "L" in this set
16	XOUT	O	Main system clock output terminal (16.9344 MHz)
17	XIN	I	Main system clock input terminal (16.9344 MHz)
18	SXOUT	O	Sub system clock output terminal Not used (open)
19	SXIN	I	Sub system clock input terminal Not used (fixed at "L")
20	COUT	O	Not used (open)
21	VDD	—	Power supply terminal (+2V) (digital system)
22	VSS	—	Ground terminal (digital system)
23	HOLD SW	I	HOLD switch (S802) input terminal "L": hold off, "H": hold on
24	XRFSW	O	Standby control signal output to the CXA2523ATQ (IC501) "L": standby
25, 26	NC	—	Not used (open)
27	SQSY	I	Subcode Q sync (SCOR) input from the CXD2663GA (IC601) "L" is input every 13.3 msec Almost all, "H" is input
28	XINT	I	Interrupt status input from the CXD2663GA (IC601)
29, 30	DBB0, DBB1	I	DIGITAL MEGABASS switch (S301) input terminal *1
31	OPR LED	O	OPERATE LED (D801) drive signal output terminal "H": LED on
32	NC	—	Not used (open)
33	ADJUST	I	Setting terminal for the test mode "L": test mode, Normally: fixed at "H"
34	RMC VCON	O	Remote commander power supply voltage select signal output to the DC/DC converter circuit
35	SBUS CLK	O	SBB serial clock signal output terminal Not used (open)
36	SBUS DATA	I/O	SBB serial data input/output terminal Not used (open)
37	LD ON	O	Laser diode on/off control signal output to the automatic power control circuit "L": laser off, "H": laser on
38	SLD 1 MON	I	Sled servo timing signal input from the MPC17A55VF (IC551)
39	SLD 2 MON	I	Sled servo timing signal input from the MPC17A55VF (IC551)
40	AVDD	—	Power supply terminal (analog system) Not used (open)
41	VPP	—	Test terminal (fixed at "L")
42	CLV VCON	O	Spindle servo drive voltage control signal output to the MPC17A55VF (IC551)
43	APC REF	O	Laser power control signal output terminal Not used (open)
44	V28 CON	O	Power supply voltage adjustment PWM signal output to the MPC1830ADTB (IC901)
45	CLV U MON	I	Spindle servo (U) timing signal input from the MPC17A55VF (IC551)

Pin No.	Pin Name	I/O	Description
46	CLV V MON	I	Spindle servo (V) timing signal input from the MPC17A55VF (IC551)
47	CLV W MON	I	Spindle servo (W) timing signal input from the MPC17A55VF (IC551)
48	CLV U CON	I	Spindle servo (U) drive signal input from the MPC17A55VF (IC551) Not used
49	CLV V CON	I	Spindle servo (V) drive signal input from the MPC17A55VF (IC551) Not used
50	CLV W CON	I	Spindle servo (W) drive signal input from the MPC17A55VF (IC551) Not used
51	AVLS SW	I	AVLS switch (S803) input terminal “L”: LIMIT, “H”: NORM
52	SENSE	I	Internal status (SENSE) input from the CXD2663GA (IC601)
53	NC	—	Not used (open)
54	MTFLGL	I	Muting applied to analog signal output in non-signal status causes the signal to be “H” automatically Not used
55	MTFLGR	I	Muting applied to analog signal output in non-signal status causes the signal to be “H” automatically Not used
56	MNT0	I	Signal indicating the speed follow-up spinning mode input from the CXD2663GA (IC601) “H”: speed follow-up spinning mode
57	MNT1	I	Sled motor operation monitor signal input from the CXD2663GA (IC601) “H”: monitor drive
58	MNT2	I	Speed limiter signal input from the CXD2663GA (IC601) “L”: limiter on
59	MNT3	I	Window signal to detect an inverse trigger edge input from the CXD2663GA (IC601) “H”: edge detectable
60	BEEP	O	Beep sound drive signal output to the headphone amplifier (IC301)
61	VSS	—	Ground terminal (digital system)
62	SPCK	O	Not used (open)
63	RMC DTCK	I/O	TSB serial communication data input/output terminal for remote commander with headphone
64	SCLK	O	Serial clock signal output to the CXD2663GA (IC601)
65	SRDT	I	Reading data input from the CXD2663GA (IC601)
66	SWDT	O	Writing data output to the CXD2663GA (IC601)
67	XLAT	O	Serial data latch pulse output to the CXD2663GA (IC601)
68	SLEEP	O	System sleep control signal output to the MPC1830ADTB (IC901) “H”: sleep on
69	XWK CLR	O	Wauk up factor clear signl output to the MPC17A55VF (IC551) and MPC1830ADTB (IC901) “L” active
70	HP MUTE	O	Muting on/off control signal output to the headphone amplifier (IC301) “H”: muting on
71	HP STBY	O	Standby on/off control signal output to the headphone amplifier (IC301) “L”: standby mode, “H”: amplifier on
72	NC	—	Not used (open)
73	NV DI	I	Serial data input from the EEPROM (IC802)
74	NV DO	O	Serial data output to the EEPROM (IC802)
75	NV CLK	O	Serial clock signal output to the EEPROM (IC802)
76	NV CS1	O	Chip select signal output to the EEPROM (IC802)
77, 78	NC	—	Not used (open)
79	VDD	—	Power supply terminal (+2V) (digital system)
80	VSS	—	Ground terminal (digital system)

*1 DIGITAL MEGABASS switch (S301)

Terminal	Switch	0 (OFF)	1 (MID)	2 (MAX)
	DBB0 (pin ㉙)	“H”	“L”	“H”
	DBB1 (pin ㉚)	“H”	“H”	“L”

SECTION 7 EXPLODED VIEWS

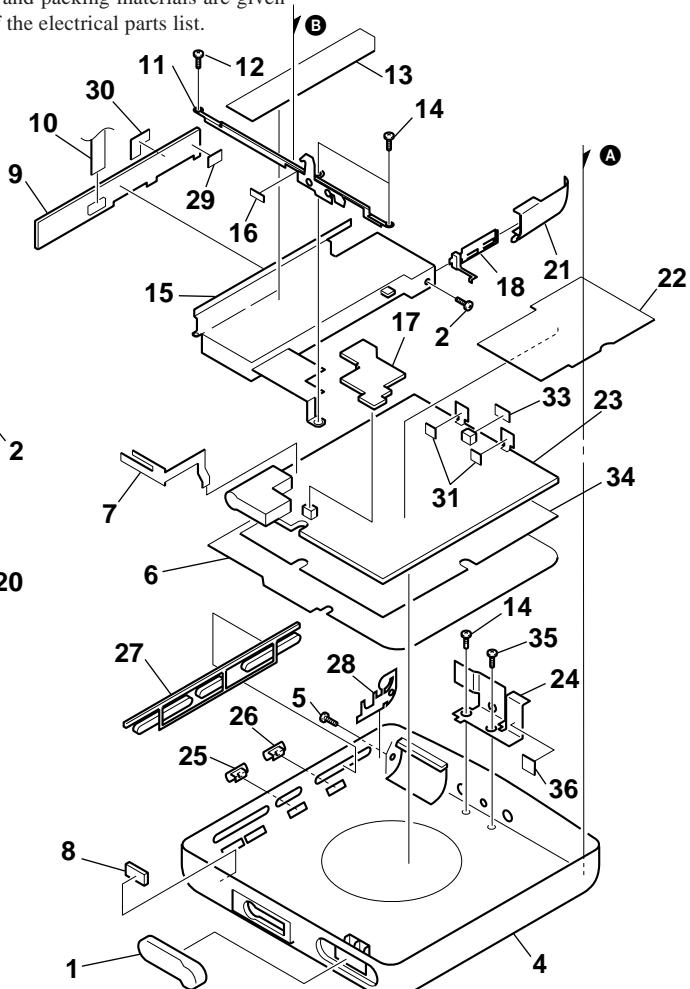
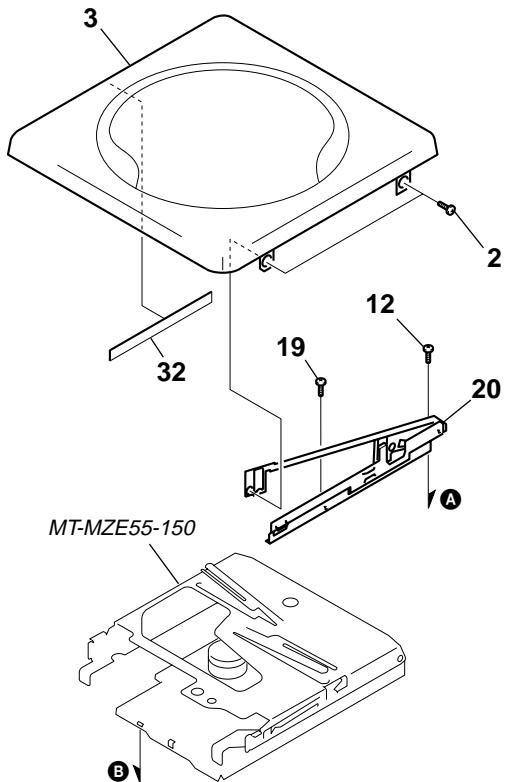
NOTE:

- -XX and -X mean standardized parts, so they may have some difference from the original one.
- Color Indication of Appearance Parts Example:
KNOB, BALANCE (WHITE) . . . (RED)
↑ ↑
Parts Color Cabinet's Color

- Items marked "*" are not stocked since they are seldom required for routine service. Some delay should be anticipated when ordering these items.
- The mechanical parts with no reference number in the exploded views are not supplied.
- Accessories and packing materials are given in the last of the electrical parts list.

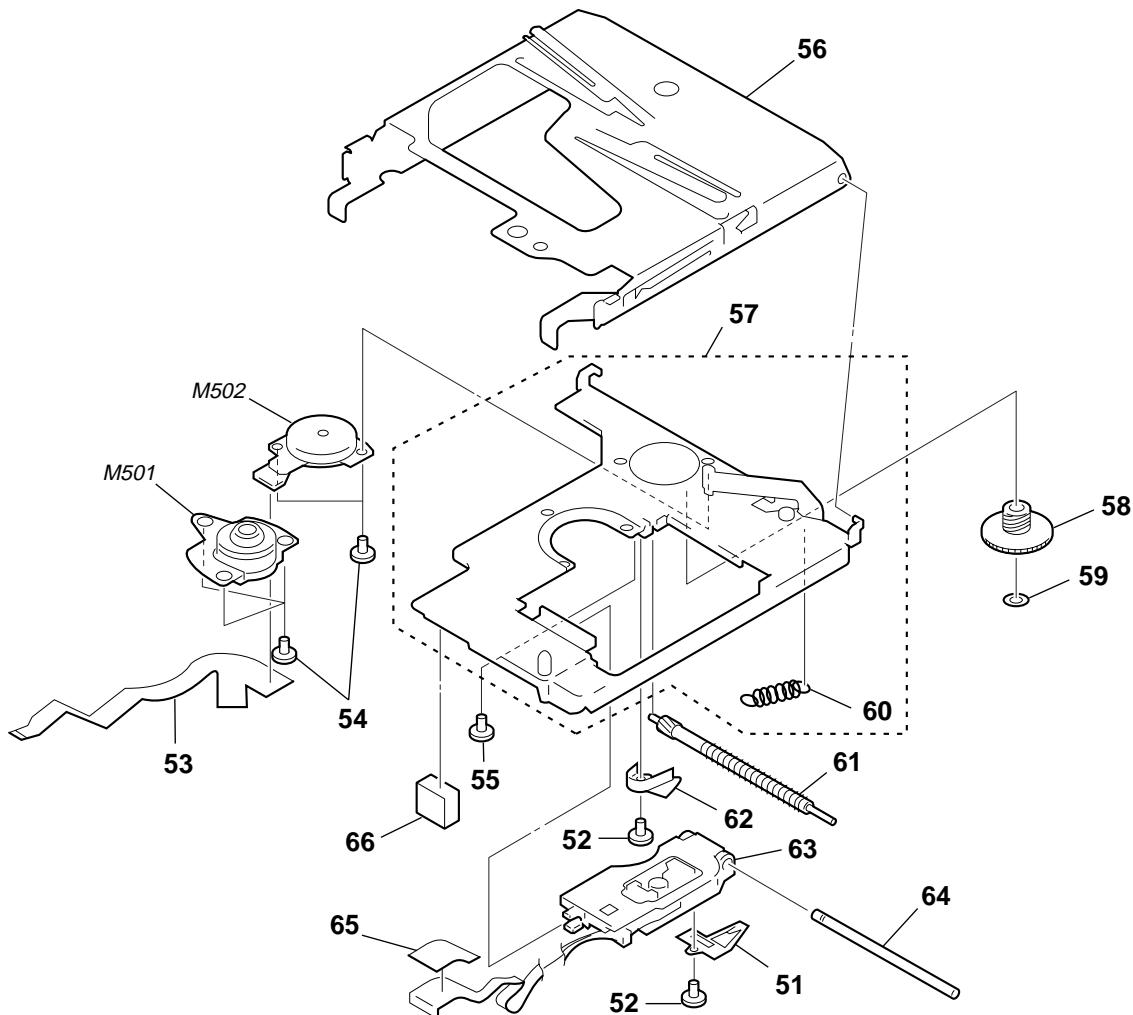
The components identified by mark \triangle or dotted line with mark \triangle are critical for safety. Replace only with part number specified.

(1) MAIN SECTION



Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
1	4-219-842-01	KNOB, OPEN		19	4-222-800-01	SCREW (1.4X2)	
2	4-963-883-21	SCREW (M1.4), PRECISION PAN		20	X-4951-548-1	PLATE (R) ASSY, FULCRUM	
3	X-4951-977-1	LID ASSY (S), UPPER (SILVER)		21	4-219-833-01	LID, BATTERY CASE (BLUE)	
3	X-4951-978-1	LID ASSY (S), UPPER (BLUE)		21	4-219-833-11	LID, BATTERY CASE (SILVER)	
3	X-4951-979-1	LID ASSY (S), UPPER (BLACK)		21	4-219-833-21	LID, BATTERY CASE (BLACK)	
4	X-4951-974-1	PANEL ASSY (S), BOTTOM (SILVER)		22	4-212-871-01	SHEET, BLIND	
4	X-4951-975-1	PANEL ASSY (S), BOTTOM (BLUE)		23	A-3323-244-A	MAIN BOARD, COMPLETE	
4	X-4951-976-1	PANEL ASSY (S), BOTTOM (BLACK)		24	4-219-843-01	BRACKET (CASE)	
5	3-349-825-21	SCREW		25	4-219-840-01	KNOB (MB) (BLUE)	
6	4-223-224-01	SHEET (PANEL) (BLUE)		25	4-219-840-11	KNOB (MB) (SILVER)	
6	4-223-224-11	SHEET (PANEL) (SILVER)		25	4-219-840-21	KNOB (MB) (BLACK)	
6	4-223-224-21	SHEET (PANEL) (BLACK)		26	4-219-836-01	KNOB (AVLS) (BLUE)	
7	4-212-895-01	TERMINAL BOARD (MINUS)		26	4-219-836-11	KNOB (AVLS) (SILVER)	
8	4-214-158-01	DAMPER (-)		26	4-219-836-21	KNOB (AVLS) (BLACK)	
9	A-3322-066-A	SW BOARD, COMPLETE		27	4-219-835-01	BUTTON, CONTROL	
10	1-674-262-11	SWITCH FLEXIBLE BOARD		28	X-4951-964-1	PLATE (L) ASSY, FULCRUM	
11	X-4951-549-1	SLIDER ASSY, OPEN		29	4-223-563-01	SHEET (CHASSIS)	
12	3-015-033-01	SCREW (B1.4X3), TAPPING		30	4-223-564-01	SHEET (CONTROL), CONDUCTIVE	
13	4-213-092-01	LABEL, CAUTION		31	4-223-223-01	SHEET (TERMINAL)	
14	3-895-823-01	SCREW (B1.4X2.3), TAPPING		32	4-223-221-01	SHEET (BRACKET)	
15	4-219-834-01	CASE, BATTERY		33	4-223-756-01	SHEET (OPEN)	
16	4-223-757-01	SHEET (SLIDER)		34	4-223-222-01	SHEET, CONDUCTIVE	
17	A-3322-068-A	AUDIO BOARD, COMPLETE		35	3-890-155-01	PAN (DIA. 1.4)	
18	X-4950-411-1	TERMINAL (PLUS) ASSY, BATTERY		36	4-224-063-01	SHEET	

**(2) MECHANISM DECK SECTION
(MT-MZE55-150)**



The components identified by mark \triangle or dotted line with mark \triangle are critical for safety.
Replace only with part number specified.

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
51	4-982-561-11	SPRING, RACK		60	4-986-811-01	SPRING (EJECT), TENSION	
52	4-963-883-61	SCREW (M1.4), PRECISION PAN		61	X-4948-793-1	LEAD ASSY	
53	1-670-707-11	CLV FLEXIBLE BOARD		62	4-212-899-01	SPRING, THRUST	
54	4-963-883-21	SCREW (M1.4), PRECISION PAN	\triangle	63	X-4949-164-1	OPTICAL PICK-UP ASSY (ODX-1B)	
55	3-349-825-82	SCREW, PRECISION		64	4-214-478-01	SHAFT, MAIN	
56	4-212-896-01	HOLDER		65	4-214-207-01	SHEET (OP)	
57	X-4950-414-1	CHASSIS ASSY		66	4-222-799-01	SPACER (OP FLEXIBLE)	
58	4-982-555-01	GEAR (A)		M501	8-835-594-02	MOTOR, DC SSM-01C03A/C-N (SPINDLE)	
59	4-965-893-01	WASHER, GEAR (A) STOPPER		M502	1-698-764-21	MOTOR, SLED (SLED)	

SECTION 8 ELECTRICAL PARTS LIST

AUDIO
MAIN
NOTE:

- Due to standardization, replacements in the parts list may be different from the parts specified in the diagrams or the components used on the set.
- -XX and -X mean standardized parts, so they may have some difference from the original one.
- **RESISTORS**
All resistors are in ohms.
METAL: Metal-film resistor.
METAL OXIDE: Metal oxide-film resistor.
F: nonflammable

- Items marked “*” are not stocked since they are seldom required for routine service. Some delay should be anticipated when ordering these items.

SEMICONDUCTORS

 In each case, u: μ , for example:

 uA... : μ A... uPA... : μ PA...

 uPB... : μ PB... uPC... : μ PC...

 uPD... : μ PD...

CAPACITORS

 uF: μ F

COILS

 uH: μ H

 The components identified by mark \triangle or dotted line with mark \triangle are critical for safety. Replace only with part number specified.

When indicating parts by reference number, please include the board.

Ref. No.	Part No.	Description			Remark	Ref. No.	Part No.	Description			Remark						
	A-3322-068-A	AUDIO BOARD, COMPLETE						< CAPACITOR >									

< CAPACITOR >																	
C102	1-125-899-11	TANTALUM CHIP	220uF	20%	4V	C101	1-109-935-11	TANTALUM CHIP	4.7uF	20%	6.3V						
C103	1-115-467-11	CERAMIC CHIP	0.22uF	10%	10V	C104	1-162-969-11	CERAMIC CHIP	0.0068uF	10%	25V						
C202	1-125-899-11	TANTALUM CHIP	220uF	20%	4V	C201	1-109-935-11	TANTALUM CHIP	4.7uF	20%	6.3V						
C203	1-115-467-11	CERAMIC CHIP	0.22uF	10%	10V	C204	1-162-969-11	CERAMIC CHIP	0.0068uF	10%	25V						
C301	1-107-826-11	CERAMIC CHIP	0.1uF	10%	16V	C308	1-164-156-11	CERAMIC CHIP	0.1uF		25V						
C302	1-125-838-11	CERAMIC CHIP	2.2uF	10%	6.3V	C501	1-117-919-11	TANTALUM CHIP	10uF	20%	6.3V						
C303	1-135-259-11	TANTALUM CHIP	10uF	20%	6.3V	C502	1-117-919-11	TANTALUM CHIP	10uF	20%	6.3V						
C304	1-109-935-11	TANTALUM CHIP	4.7uF	20%	6.3V	C503	1-162-966-11	CERAMIC CHIP	0.0022uF	10%	50V						
C305	1-125-837-91	CERAMIC CHIP	1uF	10%	6.3V	C504	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V						
C306	1-135-259-11	TANTALUM CHIP	10uF	20%	6.3V	C505	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V						
< CONNECTOR >																	
* CN302	1-750-281-31	CONNECTOR, BOARD TO BOARD	10P			C506	1-164-677-11	CERAMIC CHIP	0.033uF	10%	16V						
< IC >																	
IC301	8-759-598-15	IC	TA2131FL (EL)			C507	1-107-826-11	CERAMIC CHIP	0.1uF	10%	16V						
< TRANSISTOR >																	
Q301	8-729-037-52	TRANSISTOR	2SD2216J-QR (TX).SO			C508	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V						
< RESISTOR >																	
R103	1-216-829-11	METAL CHIP	4.7K	5%	1/16W	C509	1-109-982-11	CERAMIC CHIP	1uF	10%	10V						
R105	1-216-835-11	METAL CHIP	15K	5%	1/16W	C510	1-162-965-11	CERAMIC CHIP	0.0015uF	10%	50V						
R106	1-216-829-11	METAL CHIP	4.7K	5%	1/16W	C511	1-162-967-11	CERAMIC CHIP	0.0033uF	10%	50V						
R107	1-216-797-11	METAL CHIP	10	5%	1/16W	C512	1-115-467-11	CERAMIC CHIP	0.22uF	10%	10V						
R203	1-216-829-11	METAL CHIP	4.7K	5%	1/16W	C513	1-107-826-11	CERAMIC CHIP	0.1uF	10%	16V						
R205	1-216-835-11	METAL CHIP	15K	5%	1/16W	C514	1-162-969-11	CERAMIC CHIP	0.0068uF	10%	25V						
R206	1-216-829-11	METAL CHIP	4.7K	5%	1/16W	C515	1-107-826-11	CERAMIC CHIP	0.1uF	10%	16V						
R207	1-216-797-11	METAL CHIP	10	5%	1/16W	C516	1-127-569-11	TANTALUM CHIP	100uF	20%	4V						
R301	1-216-831-11	METAL CHIP	6.8K	5%	1/16W	C518	1-127-569-11	TANTALUM CHIP	100uF	20%	4V						
R302	1-216-849-11	METAL CHIP	220K	5%	1/16W	C519	1-165-176-11	CERAMIC CHIP	0.047uF	10%	16V						
R305	1-216-803-11	METAL CHIP	33	5%	1/16W	C520	1-165-176-11	CERAMIC CHIP	0.047uF	10%	16V						

	A-3323-244-A	MAIN BOARD, COMPLETE				C521	1-164-156-11	CERAMIC CHIP	0.1uF		25V						

4-219-844-01	TERMINAL					C522	1-117-919-11	TANTALUM CHIP	10uF	20%	6.3V						
						C524	1-164-156-11	CERAMIC CHIP	0.1uF		25V						
						C525	1-164-156-11	CERAMIC CHIP	0.1uF		25V						
						C526	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V						
						C527	1-164-156-11	CERAMIC CHIP	0.1uF		25V						
						C528	1-164-156-11	CERAMIC CHIP	0.1uF		25V						
						C529	1-117-919-11	TANTALUM CHIP	10uF	20%	6.3V						
						C551	1-162-964-11	CERAMIC CHIP	0.001uF	10%	50V						
						C552	1-162-964-11	CERAMIC CHIP	0.001uF	10%	50V						
						C553	1-135-238-21	TANTALUM CHIP	6.8uF	20%	10V						
						C554	1-135-238-21	TANTALUM CHIP	6.8uF	20%	10V						
						C555	1-107-765-11	TANTALUM CHIP	3.3uF	20%	16V						
						C556	1-107-765-11	TANTALUM CHIP	3.3uF	20%	16V						
						C557	1-117-720-11	CERAMIC CHIP	4.7uF		10V						
						C558	1-127-895-11	TANTALUM CHIP	22uF	20%	4V						
						C559	1-125-838-11	CERAMIC CHIP	2.2uF	10%	6.3V						
						C560	1-125-838-11	CERAMIC CHIP	2.2uF	10%	6.3V						

MAIN

Ref. No.	Part No.	Description		Remark	Ref. No.	Part No.	Description	Remark
C561	1-125-838-11	CERAMIC CHIP	2.2uF	10%	6.3V	* CN501	1-778-168-11	CONNECTOR, FFC/FPC (ZIF) 20P
C562	1-109-982-11	CERAMIC CHIP	1uF	10%	10V	* CN551	1-793-124-21	CONNECTOR, FPC (ZIP) 8P
C563	1-117-720-11	CERAMIC CHIP	4.7uF	10V		* CN801	1-793-327-21	CONNECTOR, FPC
C564	1-127-569-11	TANTALUM CHIP	100uF	20%	4V			< DIODE >
C565	1-135-259-11	TANTALUM CHIP	10uF	20%	6.3V	D151	8-719-017-58	DIODE MA8068
C568	1-127-760-11	CAPACITOR	4.7uF	10%	6.3V	D251	8-719-017-58	DIODE MA8068
C569	1-127-760-11	CAPACITOR	4.7uF	10%	6.3V	D351	8-719-017-58	DIODE MA8068
C570	1-127-760-11	CAPACITOR	4.7uF	10%	6.3V	D841	8-719-066-17	DIODE FTZ6.8E-T148
C572	1-127-760-11	CAPACITOR	4.7uF	10%	6.3V	D901	8-719-420-51	DIODE MA729
C573	1-127-760-11	CAPACITOR	4.7uF	10%	6.3V	D902	8-719-066-16	DIODE RB491D-T146
C574	1-127-760-11	CAPACITOR	4.7uF	10%	6.3V	D903	8-719-420-51	DIODE MA729
C603	1-117-720-11	CERAMIC CHIP	4.7uF	10V				< FERRITE BEAD >
C604	1-164-156-11	CERAMIC CHIP	0.1uF	25V		FB602	1-414-227-11	FERRITE BEAD INDUCTOR CHIP 0uH
C605	1-162-917-11	CERAMIC CHIP	15PF	5%	50V	FB841	1-414-228-11	FERRITE BEAD INDUCTOR CHIP 0uH
C606	1-162-919-11	CERAMIC CHIP	22PF	5%	50V	FB842	1-414-228-11	FERRITE BEAD INDUCTOR CHIP 0uH
C607	1-164-156-11	CERAMIC CHIP	0.1uF	25V				< IC >
C608	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V	IC501	8-752-093-82	IC CXA2523ATQ-T4
C609	1-125-891-11	CERAMIC CHIP	0.47uF	10%	10V	IC502	8-759-581-57	IC MAX4330EUK-TG069
C610	1-162-962-11	CERAMIC CHIP	470PF	10%	50V	IC503	8-759-599-61	IC XC62FP2202MR
C611	1-125-891-11	CERAMIC CHIP	0.47uF	10%	10V	IC504	8-759-488-26	IC XC62FP2002MR
C612	1-164-156-11	CERAMIC CHIP	0.1uF	25V		IC551	8-759-390-25	IC MPC17A55FTA
C614	1-164-245-11	CERAMIC CHIP	0.015uF	10%	25V	IC552	8-759-358-40	IC TLC372CPW-E20
C615	1-164-156-11	CERAMIC CHIP	0.1uF	25V		IC601	_____	IC CXD2663GA
C617	1-117-919-11	TANTALUM CHIP	10uF	20%	6.3V	IC801	8-759-596-10	IC RU6915MF-0001
C618	1-115-156-11	CERAMIC CHIP	1uF	10V		IC802	8-759-449-23	IC AK93C55AV-L
C619	1-115-156-11	CERAMIC CHIP	1uF	10V		IC901	8-759-538-57	IC MPC1830ADTB
C620	1-164-156-11	CERAMIC CHIP	0.1uF	25V		IC902	8-759-599-62	IC XC6383C281MR
C621	1-117-919-11	TANTALUM CHIP	10uF	20%	6.3V			< JACK >
C801	1-162-962-11	CERAMIC CHIP	470PF	10%	50V	J301	1-779-867-61	JACK (◎ REMOTE)
C803	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V			< COIL >
C804	1-162-964-11	CERAMIC CHIP	0.001uF	10%	50V	L501	1-412-006-31	INDUCTOR CHIP 10uH
C805	1-164-156-11	CERAMIC CHIP	0.1uF	25V		L551	1-412-031-11	INDUCTOR CHIP 47uH
C807	1-115-156-11	CERAMIC CHIP	1uF	10V		L552	1-412-031-11	INDUCTOR CHIP 47uH
C808	1-164-156-11	CERAMIC CHIP	0.1uF	25V		L553	1-412-030-11	INDUCTOR CHIP 22uH
C809	1-164-156-11	CERAMIC CHIP	0.1uF	25V		L554	1-412-030-11	INDUCTOR CHIP 22uH
C813	1-117-232-11	TANTALUM CHIP	22uF	20%	4V			
C831	1-164-156-11	CERAMIC CHIP	0.1uF	25V		L555	1-412-030-11	INDUCTOR CHIP 22uH
C832	1-162-964-11	CERAMIC CHIP	0.001uF	10%	50V	L556	1-414-410-21	SMALL TYPE INDUCTOR (SMD TYPE) 10uH
C833	1-162-964-11	CERAMIC CHIP	0.001uF	10%	50V	L901	1-412-032-11	INDUCTOR CHIP 100uH
C834	1-164-156-11	CERAMIC CHIP	0.1uF	25V		L902	1-419-131-21	COIL, CHOKE 15uH
C901	1-162-964-11	CERAMIC CHIP	0.001uF	10%	50V	L903	1-414-410-21	SMALL TYPE INDUCTOR (SMD TYPE) 10uH
C902	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V	L904	1-414-406-41	INDUCTOR (SMD) 220uH
C903	1-107-826-11	CERAMIC CHIP	0.1uF	10%	16V			< TRANSISTOR >
C904	1-109-982-11	CERAMIC CHIP	1uF	10%	10V			
C905	1-162-964-11	CERAMIC CHIP	0.001uF	10%	50V	Q501	8-729-049-81	FET SSM3K01F-TE85L
C906	1-107-826-11	CERAMIC CHIP	0.1uF	10%	16V	Q502	8-729-046-90	TRANSISTOR 2SB970- (TX).SO
C907	1-107-826-11	CERAMIC CHIP	0.1uF	10%	16V	Q503	8-729-425-46	TRANSISTOR XP4315-TXE
C908	1-109-982-11	CERAMIC CHIP	1uF	10%	10V	Q551	8-729-904-87	TRANSISTOR 2SB1197K-R
C910	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V	Q552	8-729-929-11	TRANSISTOR DTC143ZE-TL
C911	1-135-259-11	TANTALUM CHIP	10uF	20%	6.3V			
C912	1-135-259-11	TANTALUM CHIP	10uF	20%	6.3V	Q901	8-729-049-81	FET SSM3K01F-TE85L
C918	1-164-156-11	CERAMIC CHIP	0.1uF	25V		Q902	8-729-049-81	FET SSM3K01F-TE85L
C919	1-164-156-11	CERAMIC CHIP	0.1uF	25V		Q903	8-729-929-11	TRANSISTOR DTC143ZE-TL
C920	1-164-156-11	CERAMIC CHIP	0.1uF	25V				< CONNECTOR >
* CN301 1-750-316-31 CONNECTOR, BOARD TO BOARD 10P								

□ Replacement of CXD2663GA (IC601) used in this set requires a special tool. Therefore, it cannot be replaced.

MAIN

SW

Ref. No.	Part No.	Description		Remark	Ref. No.	Part No.	Description		Remark								
< RESISTOR >																	
R101	1-216-819-11	METAL CHIP	680	5%	1/16W	R819	1-216-853-11	METAL CHIP	470K	5%	1/16W						
R201	1-216-819-11	METAL CHIP	680	5%	1/16W	R821	1-216-857-11	METAL CHIP	1M	5%	1/16W						
R501	1-216-831-11	METAL CHIP	6.8K	5%	1/16W	R841	1-216-809-11	METAL CHIP	100	5%	1/16W						
R502	1-216-859-11	RES, CHIP	1.5M	5%	1/16W	R842	1-216-809-11	METAL CHIP	100	5%	1/16W						
R503	1-216-853-11	METAL CHIP	470K	5%	1/16W	R901	1-216-845-11	METAL CHIP	100K	5%	1/16W						
R504	1-216-825-11	METAL CHIP	2.2K	5%	1/16W	R902	1-216-849-11	METAL CHIP	220K	5%	1/16W						
R505	1-216-825-11	METAL CHIP	2.2K	5%	1/16W	R903	1-216-863-11	RES, CHIP	3.3M	5%	1/16W						
R506	1-216-825-11	METAL CHIP	2.2K	5%	1/16W	R904	1-216-845-11	METAL CHIP	100K	5%	1/16W						
R507	1-216-835-11	METAL CHIP	15K	5%	1/16W	R905	1-216-857-11	METAL CHIP	1M	5%	1/16W						
R508	1-216-835-11	METAL CHIP	15K	5%	1/16W	R909	1-216-847-11	METAL CHIP	150K	5%	1/16W						
R509	1-216-845-11	METAL CHIP	100K	5%	1/16W	R910	1-218-871-11	RES, CHIP	10K	0.5%	1/16W						
R510	1-216-843-11	METAL CHIP	68K	5%	1/16W	R911	1-216-833-11	RES, CHIP	10K	5%	1/16W						
R511	1-216-833-11	RES, CHIP	10K	5%	1/16W	R912	1-216-864-11	METAL CHIP	0	5%	1/16W						
R512	1-216-843-11	METAL CHIP	68K	5%	1/16W	R913	1-216-819-11	METAL CHIP	680	5%	1/16W						
R513	1-216-864-11	METAL CHIP	0	5%	1/16W	R914	1-216-857-11	METAL CHIP	1M	5%	1/16W						
R514	1-216-864-11	METAL CHIP	0	5%	1/16W	R915	1-216-857-11	METAL CHIP	1M	5%	1/16W						
R515	1-216-821-11	METAL CHIP	1K	5%	1/16W	R916	1-216-859-11	RES, CHIP	1.5M	5%	1/16W						
R517	1-216-811-11	METAL CHIP	150	5%	1/16W	R918	1-216-845-11	METAL CHIP	100K	5%	1/16W						
R518	1-218-446-11	METAL CHIP	1	5%	1/16W	< COMPOSITION CIRCUIT BLOCK >											
R519	1-216-857-11	METAL CHIP	1M	5%	1/16W	RB551	1-233-961-11	RES, NETWORK (CHIP TYPE) 1K									
R521	1-216-833-11	RES, CHIP	10K	5%	1/16W	RB552	1-233-979-11	RES, NETWORK (CHIP TYPE) 1M									
R522	1-216-857-11	METAL CHIP	1M	5%	1/16W	RB601	1-233-981-21	RES, NETWORK (CHIP TYPE) 0									
R523	1-216-821-11	METAL CHIP	1K	5%	1/16W	RB801	1-233-977-11	RES, NETWORK (CHIP TYPE) 470K									
R524	1-216-833-11	RES, CHIP	10K	5%	1/16W	RB802	1-233-969-11	RES, NETWORK (CHIP TYPE) 22K									
R525	1-216-833-11	RES, CHIP	10K	5%	1/16W	RB803	1-233-973-11	RES, NETWORK (CHIP TYPE) 100K									
R526	1-216-833-11	RES, CHIP	10K	5%	1/16W	< VIBRATOR >											
R553	1-216-833-11	RES, CHIP	10K	5%	1/16W	X601	1-781-556-21	VIBRATOR, CRYSTAL (22.5792MHz)									
R554	1-216-833-11	RES, CHIP	10K	5%	1/16W	X801	1-767-621-11	VIBRATOR, CERAMIC (16.9344MHz)									
R555	1-216-809-11	METAL CHIP	100	5%	1/16W	*****											
R556	1-216-853-11	METAL CHIP	470K	5%	1/16W	A-3322-066-A SW BOARD, COMPLETE											
R602	1-216-821-11	METAL CHIP	1K	5%	1/16W	*****											
R604	1-216-841-11	METAL CHIP	47K	5%	1/16W	< CONNECTOR >											
R605	1-216-833-11	RES, CHIP	10K	5%	1/16W	* CN802	1-793-328-21	CONNECTOR, FPC									
R606	1-216-845-11	METAL CHIP	100K	5%	1/16W	< LED >											
R607	1-216-855-11	METAL CHIP	680K	5%	1/16W	D801	8-719-061-82	LED TLSU1002 (TPX1, SONY) (OPERATE)									
R610	1-216-827-11	METAL CHIP	3.3K	5%	1/16W	< RESISTOR >											
R611	1-216-857-11	METAL CHIP	1M	5%	1/16W	R614	1-216-821-11	METAL CHIP	1K	5%	1/16W						
R612	1-216-811-11	METAL CHIP	150	5%	1/16W	R615	1-216-803-11	METAL CHIP	33	5%	1/16W						
R613	1-216-821-11	METAL CHIP	1K	5%	1/16W	R616	1-216-864-11	METAL CHIP	0	5%	1/16W						
R614	1-216-821-11	METAL CHIP	1K	5%	1/16W	R617	1-216-803-11	METAL CHIP	33	5%	1/16W						
R615	1-216-803-11	METAL CHIP	33	5%	1/16W	R618	1-216-864-11	METAL CHIP	0	5%	1/16W						
R616	1-216-864-11	METAL CHIP	0	5%	1/16W	R619	1-216-825-11	METAL CHIP	2.2K	5%	1/16W						
R617	1-216-803-11	METAL CHIP	33	5%	1/16W	R620	1-216-831-11	METAL CHIP	4.7K	5%	1/16W						
R618	1-216-864-11	METAL CHIP	0	5%	1/16W	R621	1-216-831-11	METAL CHIP	6.8K	5%	1/16W						
R620	1-216-864-11	METAL CHIP	0	5%	1/16W	R622	1-216-835-11	METAL CHIP	15K	5%	1/16W						
R801	1-216-845-11	METAL CHIP	100K	5%	1/16W	R623	1-216-839-11	METAL CHIP	33K	5%	1/16W						
R802	1-216-845-11	METAL CHIP	100K	5%	1/16W	< SWITCH >											
R803	1-216-853-11	METAL CHIP	470K	5%	1/16W	S301	1-762-079-11	SWITCH, SLIDE (DIGITAL MEGABASS)									
R804	1-216-833-11	RES, CHIP	10K	5%	1/16W	S801	1-771-483-21	SWITCH, PUSH (1KEY) (OPEN/CLOSE)									
R805	1-216-853-11	METAL CHIP	470K	5%	1/16W	S802	1-572-922-11	SWITCH, SLIDE (HOLD)									
R806	1-218-895-11	RES, CHIP	100K	0.5%	1/16W	S803	1-762-078-11	SWITCH, SLIDE (AVLS)									
R807	1-218-895-11	RES, CHIP	100K	0.5%	1/16W	*****											
R808	1-216-825-11	METAL CHIP	2.2K	5%	1/16W	R813	1-216-833-11	METAL CHIP	10K	5%	1/16W						
R811	1-216-827-11	METAL CHIP	3.3K	5%	1/16W												
R812	1-216-841-11	METAL CHIP	47K	5%	1/16W												

<u>Ref. No.</u>	<u>Part No.</u>	<u>Description</u>	<u>Remark</u>
***** MISCELLANEOUS *****			

10	1-674-262-11	SWITCH FLEXIBLE BOARD	
53	1-670-707-11	CLV FLEXIBLE BOARD	
△63	X-4949-164-1	OPTICAL PICK-UP ASSY (ODX-1B)	
M501	8-835-594-02	MOTOR, DC SSM-01C03A/C-N (SPINDLE)	
M502	1-698-764-21	MOTOR, SLED (SLED)	

ACCESSORIES & PACKING MATERIALS

4-221-117-01 CASE, CARRYING
4-221-753-01 STRAP, HAND (BLUE)
4-221-753-11 STRAP, HAND (SILVER)
4-221-753-21 STRAP, HAND (BLACK)
8-953-304-90 HEADPHONE MDR-E805SP

The components identified by mark \triangle or dotted line with mark \triangle are critical for safety.
Replace only with part number specified.

MZ-E80

SONY®

*E Model
Tourist Model*

SERVICE MANUAL

2000. 05

SUPPLEMENT-1

File this supplement with the service manual.

Subject: Change of Boards

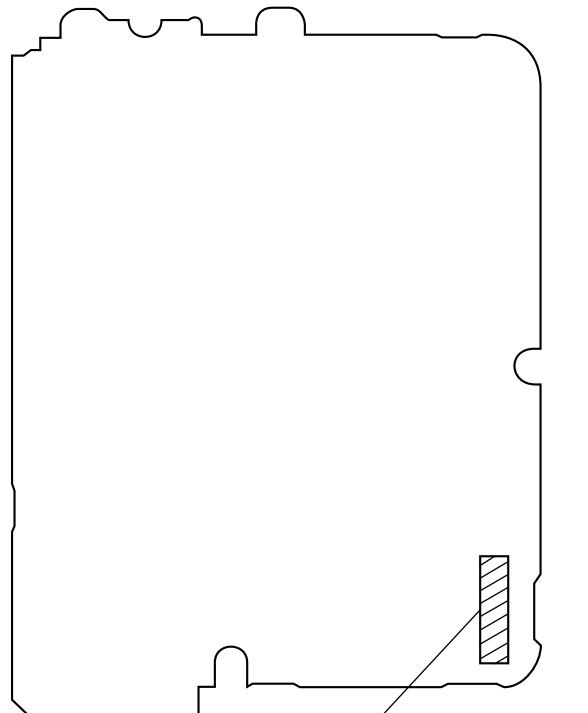
(ECN-DA800895, DA800972)

The MAIN board, AUDIO board, and SW board have been changed in the middle of production.
Printed wiring board and schematic diagram of new type, and changed parts list are described
in this Supplement-1.

Refer to original service manual (9-927-132-II) previously issued for other information.
When performing service and inspection, check the suffix of the part number of boards.

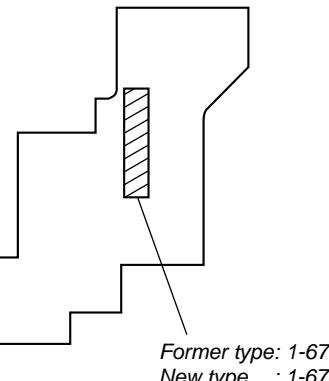
• NEW/FORMER TYPE DISCRIMINATION

- MAIN BOARD (Conductor Side) -



Former type: 1-674-351-11
New type : 1-674-351-12

- AUDIO BOARD (Component Side) -



Former type: 1-674-352-11
New type : 1-674-352-12

- SWITCH BOARD (Conductor Side) -



Former type: 1-674-263-11
New type : 1-674-263-12

• PRINTED WIRING BOARDS

• Semiconductor Location

Ref. No.	Location	Ref. No.	Location
D151	H-9	IC506	D-13
D251	G-10	IC551	D-10
D351	H-9	IC552	B-11
D801	J-15	IC601	E-13
D802	F-14	IC801	C-14
D803	F-13	IC802	D-14
D804	F-13	IC901	B-9
D841	G-11	IC902	A-13
D901	B-11	Q301	I-17
D902	F-10	Q501	F-14
D903	A-13	Q502	G-11
IC301	I-16	Q503	F-14
IC501	G-13	Q551	E-10
IC502	G-12	Q552	E-11
IC503	E-14	Q901	B-12
IC504	C-13	Q902	C-12
IC505	D-14	Q903	B-13

Note on Printed Wiring Boards:

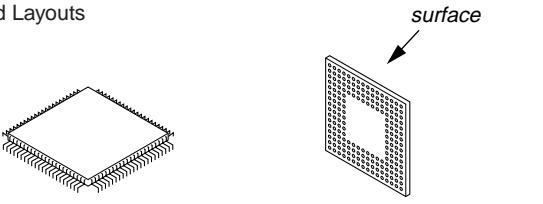
- : parts extracted from the conductor side.
- : Through hole.
- △ : internal component.
- : Pattern from the side which enables seeing.
(The other layers' patterns are not indicated.)

Caution:
Pattern face side: Parts on the pattern face side seen from
(Conductor Side)
Parts face side: Parts on the parts face side seen from
(Component Side)

- Main board is four-layer printed board.
However, the patterns of layers 2 and 3 have not been included in this diagrams.

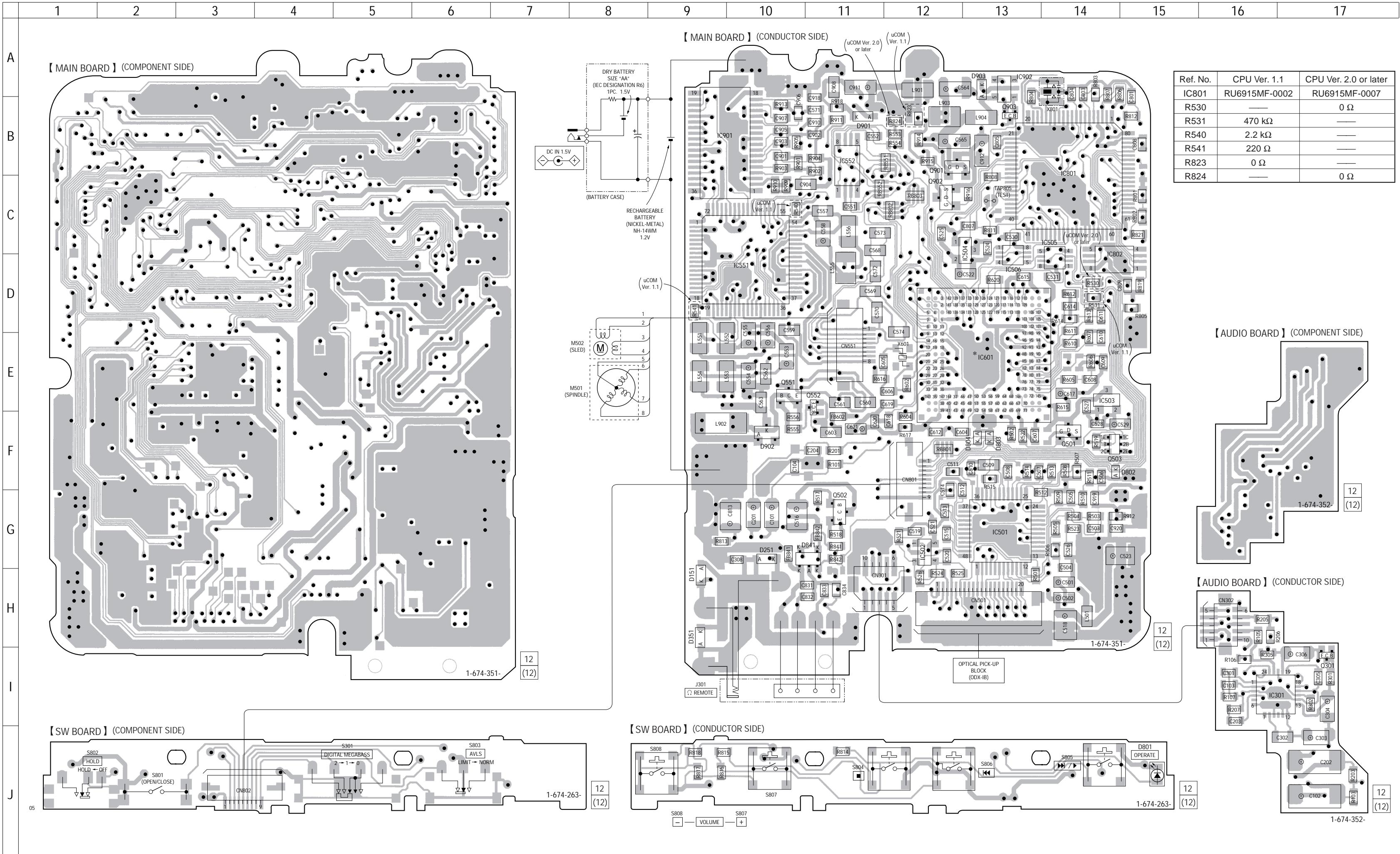
* IC601 is not replaceable

• Lead Layouts

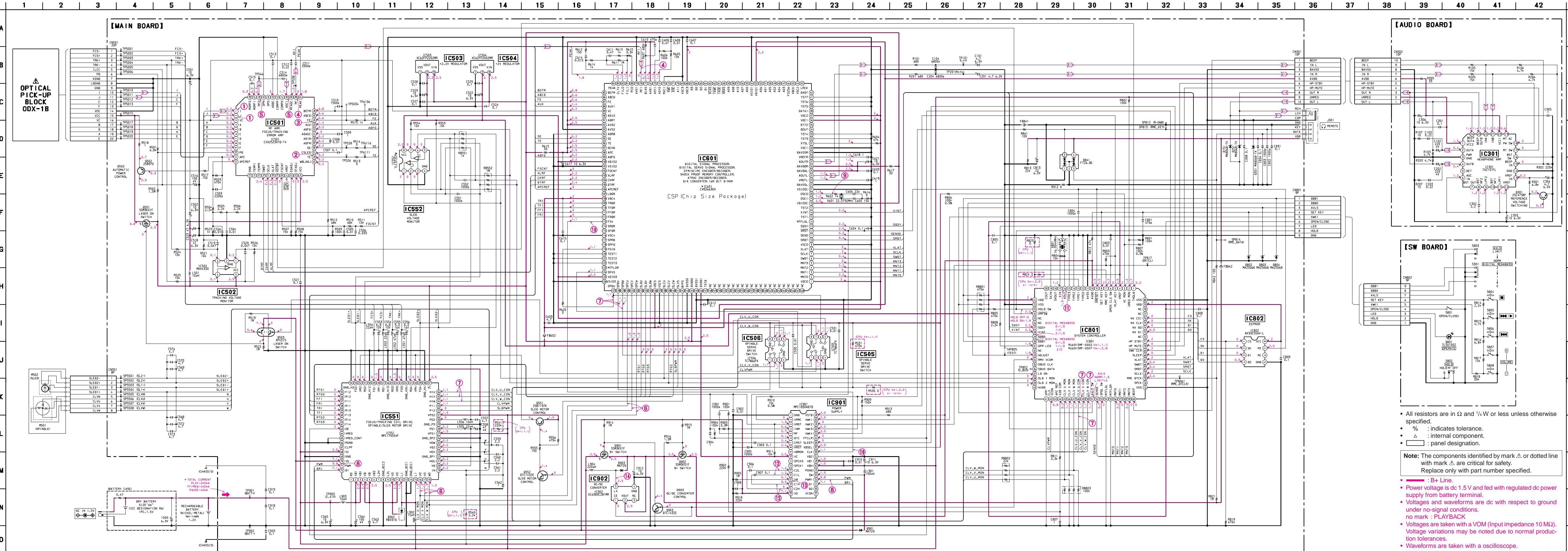


Lead layout of conventional IC

CSP (chip size package)



SCHEMATIC DIAGRAM



ble

Note on Schematic Diagram:

- All capacitors are in μF unless
50 WV or less are not indicated
and tantalums.

- Selected numbers refer to waveforms.
 - Signal path.
 -  : PLAYBACK

• ELECTRICAL PARTS LIST

NOTE:
• Due to standardization, replacements in the parts list may be different from the parts specified in the diagrams or the components used on the set.

• -XX and -X mean standardized parts, so they may have some difference from the original one.

• RESISTORS

All resistors are in ohms.

METAL: Metal-film resistor.

METAL OXIDE: Metal oxide-film resistor.

F: nonflammable

- Items marked “**” are not stocked since they are seldom required for routine service. Some delay should be anticipated when ordering these items.

• SEMICONDUCTORS

In each case, u. for example:

uA. : μ A. uPA. : μ P.A.

uPB. : μ PB. uPC. : μ PC.

uPD. : μ PD.

• CAPACITORS

uF: μ F

• COILS

uH: μ H

When indicating parts by reference number, please include the board.

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark				
A-3322-068-A AUDIO BOARD, COMPLETE											

		< CAPACITOR >									
C101	1-109-935-11	TANTALUM CHIP 4.7uF 20% 6.3V		C603	1-117-720-11	CERAMIC CHIP 4.7uF 10% 10V					
C104	1-162-969-11	CERAMIC CHIP 0.0068uF 10% 25V		C604	1-164-156-11	CERAMIC CHIP 0.1uF 25V					
C201	1-109-935-11	TANTALUM CHIP 4.7uF 20% 6.3V		C605	1-162-917-11	CERAMIC CHIP 15PF 5% 50V					
C102	1-125-899-11	TANTALUM CHIP 220uF 20% 4V		C606	1-162-919-11	CERAMIC CHIP 22PF 5% 50V					
C103	1-115-467-11	CERAMIC CHIP 0.22uF 10% 10V		C607	1-164-156-11	CERAMIC CHIP 0.1uF 25V					
C202	1-125-899-11	TANTALUM CHIP 220uF 20% 4V		C608	1-162-970-11	CERAMIC CHIP 0.01uF 10% 25V					
C203	1-115-467-11	CERAMIC CHIP 0.22uF 10% 10V		C609	1-125-891-11	CERAMIC CHIP 0.47uF 10% 10V					
C301	1-107-826-11	CERAMIC CHIP 0.1uF 10% 16V		C610	1-162-962-11	CERAMIC CHIP 470PF 10% 50V					
C302	1-125-838-11	CERAMIC CHIP 2.2uF 10% 6.3V		C611	1-125-891-11	CERAMIC CHIP 0.47uF 10% 10V					
C303	1-135-259-11	TANTALUM CHIP 10uF 20% 6.3V		C612	1-164-156-11	CERAMIC CHIP 0.1uF 25V					
C304	1-109-935-11	TANTALUM CHIP 4.7uF 20% 6.3V		C614	1-164-245-11	CERAMIC CHIP 0.015uF 10% 50V					
C305	1-125-837-11	CERAMIC CHIP 1uF 10% 6.3V		C615	1-164-156-11	CERAMIC CHIP 0.1uF 25V					
C306	1-135-259-11	TANTALUM CHIP 10uF 20% 6.3V		C617	1-117-919-11	TANTALUM CHIP 10uF 20% 6.3V					
< CONNECTOR >											
C501	1-117-919-11	TANTALUM CHIP 10uF 20% 6.3V		C618	1-115-156-11	CERAMIC CHIP 1uF 10V					
C502	1-117-919-11	TANTALUM CHIP 10uF 20% 6.3V		C619	1-115-156-11	CERAMIC CHIP 1uF 10V					
C503	1-162-966-11	CERAMIC CHIP 0.0022uF 10% 50V		C620	1-164-156-11	CERAMIC CHIP 0.1uF 25V					
C504	1-162-970-11	CERAMIC CHIP 0.01uF 10% 25V		C621	1-117-919-11	TANTALUM CHIP 10uF 20% 6.3V					
C505	1-162-970-11	CERAMIC CHIP 0.01uF 10% 25V		C622	1-162-962-11	CERAMIC CHIP 470PF 10% 50V					
C506	1-164-677-11	CERAMIC CHIP 0.0033uF 10% 16V		C623	1-162-962-11	CERAMIC CHIP 0.01uF 10% 25V					
C507	1-107-826-11	CERAMIC CHIP 0.1uF 10% 16V		C624	1-164-156-11	CERAMIC CHIP 0.1uF 25V					
C508	1-162-970-11	CERAMIC CHIP 0.01uF 10% 25V		C625	1-117-919-11	TANTALUM CHIP 10uF 20% 6.3V					
C509	1-109-982-11	CERAMIC CHIP 1uF 10% 10V		C626	1-162-965-11	CERAMIC CHIP 0.0015uF 10% 50V					
C510	1-162-965-11	CERAMIC CHIP 0.0015uF 10% 50V		C627	1-117-919-11	TANTALUM CHIP 10uF 20% 6.3V					
< IC >											
* CN302	1-750-281-31	CONNECTOR, BOARD TO BOARD 10P		IC501	8-752-093-82	IC CXA2523ATQ-T4					
< IC >											
IC301	8-759-598-15	IC TA2131FL-EL		IC502	8-759-581-57	IC MAX4330EUK-TG069					
< TRANSISTOR >											
C511	1-162-967-11	CERAMIC CHIP 0.0033uF 10% 50V		IC503	8-759-599-61	IC XC62FP2202MR					
C512	1-115-467-11	CERAMIC CHIP 0.22uF 10% 10V		IC504	8-759-488-26	IC XC62FP2002MR					
C513	1-107-826-11	CERAMIC CHIP 0.1uF 10% 16V		IC505	8-759-647-75	IC TCTW66FK (TE85R)					
C514	1-162-969-11	CERAMIC CHIP 0.0068uF 10% 25V		< IC >							
C515	1-107-826-11	CERAMIC CHIP 0.1uF 10% 16V		IC506	8-759-647-75	IC TCTW66FK (TE85R)					
C516	1-127-569-11	TANTALUM CHIP 100uF 20% 4V		IC507	1-162-964-11	CERAMIC CHIP 0.001uF 10% 50V					
C517	1-125-839-11	TANTALUM CHIP 47uF 20% 6.3V		IC508	1-162-962-11	CERAMIC CHIP 470PF 10% 50V					
C518	1-165-176-11	CERAMIC CHIP 0.047uF 10% 16V		IC509	1-162-962-11	CERAMIC CHIP 0.01uF 10% 25V					
C519	1-165-176-11	CERAMIC CHIP 0.1uF 10% 25V		IC510	1-162-964-11	CERAMIC CHIP 0.001uF 10% 50V					
C520	1-165-176-11	CERAMIC CHIP 0.047uF 10% 16V		IC511	1-162-964-11	CERAMIC CHIP 0.001uF 10% 50V					
C521	1-164-156-11	CERAMIC CHIP 0.1uF 10% 25V		IC512	1-162-964-11	CERAMIC CHIP 0.001uF 10% 50V					
R103	1-216-829-11	METAL CHIP 4.7K 5% 1/16W		IC513	1-216-864-11	METAL CHIP 0% 5% 1/16W					
R105	1-216-835-11	METAL CHIP 15K 5% 1/16W		IC514	1-216-864-11	METAL CHIP 0% 5% 1/16W					
R106	1-216-829-11	METAL CHIP 4.7K 5% 1/16W		IC515	1-216-821-11	METAL CHIP 1K 5% 1/16W					
R107	1-216-797-11	METAL CHIP 10 5% 1/16W		IC516	1-216-821-11	METAL CHIP 1K 5% 1/16W					
R203	1-216-829-11	METAL CHIP 4.7K 5% 1/16W		IC517	1-216-811-11	METAL CHIP 150 5% 1/16W					
R205	1-216-835-11	METAL CHIP 15K 5% 1/16W		IC518	1-216-846-11	METAL CHIP 1 5% 1/16W					
R206	1-216-829-11	METAL CHIP 4.7K 5% 1/16W		IC519	1-216-846-11	METAL CHIP 0% 5% 1/16W					
R207	1-216-797-11	METAL CHIP 10 5% 1/16W		IC520	1-216-833-11	METAL CHIP 10K 5% 1/16W					
R301	1-216-831-11	METAL CHIP 6.8K 5% 1/16W		IC521	1-216-833-11	METAL CHIP 10K 5% 1/16W					
R302	1-216-849-11	METAL CHIP 220K 5% 1/16W		IC522	1-216-833-11	METAL CHIP 10K 5% 1/16W					
R305	1-216-803-11	METAL CHIP 33 5% 1/16W		IC523	1-216-833-11	METAL CHIP 10K 5% 1/16W					
< RESISTOR >											
C511	1-162-964-11	CERAMIC CHIP 0.001uF 10% 50V		IC524	1-164-156-11	CERAMIC CHIP 0.1uF 25V					
C512	1-162-964-11	CERAMIC CHIP 0.001uF 10% 50V		IC525	1-162-964-11	CERAMIC CHIP 0.001uF 10% 50V					
C513	1-162-964-11	CERAMIC CHIP 0.001uF 10% 50V		IC526	1-162-970-11	CERAMIC CHIP 0.01uF 10% 25V					
C514	1-162-964-11	CERAMIC CHIP 0.001uF 10% 50V		IC527	1-164-156-11	CERAMIC CHIP 0.1uF 25V					
C515	1-162-964-11	CERAMIC CHIP 0.001uF 10% 50V		IC528	1-164-156-11	CERAMIC CHIP 0.1uF 25V					
C516	1-162-964-11	CERAMIC CHIP 0.001uF 10% 50V		IC529	1-167-919-11	TANTALUM CHIP 10uF 20% 6.3V					
C517	1-162-964-11	CERAMIC CHIP 0.001uF 10% 50V		IC530	1-162-970-11	CERAMIC CHIP 0.01uF 10% 25V					
C518	1-162-964-11	CERAMIC CHIP 0.001uF 10% 50V		IC531	1-162-970-11	CERAMIC CHIP 0.01uF 10% 25V					
C519	1-162-964-11	CERAMIC CHIP 0.001									